



Ion Beam Techniques

and their applications

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Frequently used techniques of Ion Beam Analysis

	Primary ions	Signal to detect	E_P	Depth resolution	Spatial resolution
Methods:					
ERDA	Middle-heavy ions	Atoms from the target ($1 < Z < 10$)	ca. 1 MeV/amu	yes	no
PIXE	Protons	γ	1-3 MeV	no	possible
SIMS	O, Cs Ions	Charged atoms from the target	4-12 keV	yes	yes
NRA	Light ions	p, α , γ	0.2-10 MeV	yes	no
RBS	H^+ , He^+ , He^{++}	Projektilen	1-2 MeV	yes	no

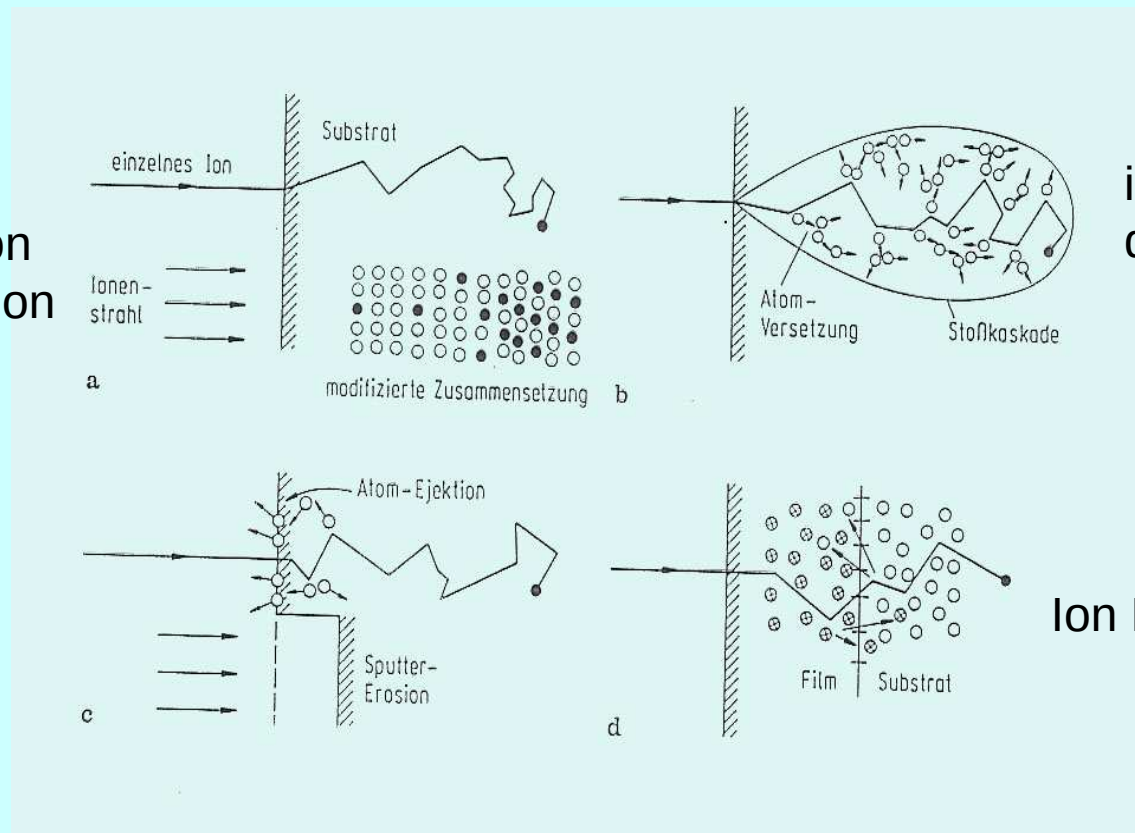
Modification of surfaces and interfaces using heavy ions

ion implantation
and/or irradiation

sputtering

irradiation induced
defects (cascades)

Ion Beam Mixing (IBM)





Possibilities in Darmstadt-Frankfurt area

50 keV implanter for different gases and metals

2.5 MeV Van de Graaff accelerator for H, He, Ne, Ar, Kr ions
modification with nuclear energy loss and ion beam analysis

High energy beams at the GSI, Darmstadt (Institute for Heavy
Ion Research)
modification with electronic energy loss

*International Conference on „Materials Science Applications of Ion Beam
Techniques“ organised already 1996 near Darmstadt
Proceedings, eds. A.G. Balogh, G. Walter, Trans Tech Publ., 1997*





Rutherford Backscattering Spectrometry (RBS)

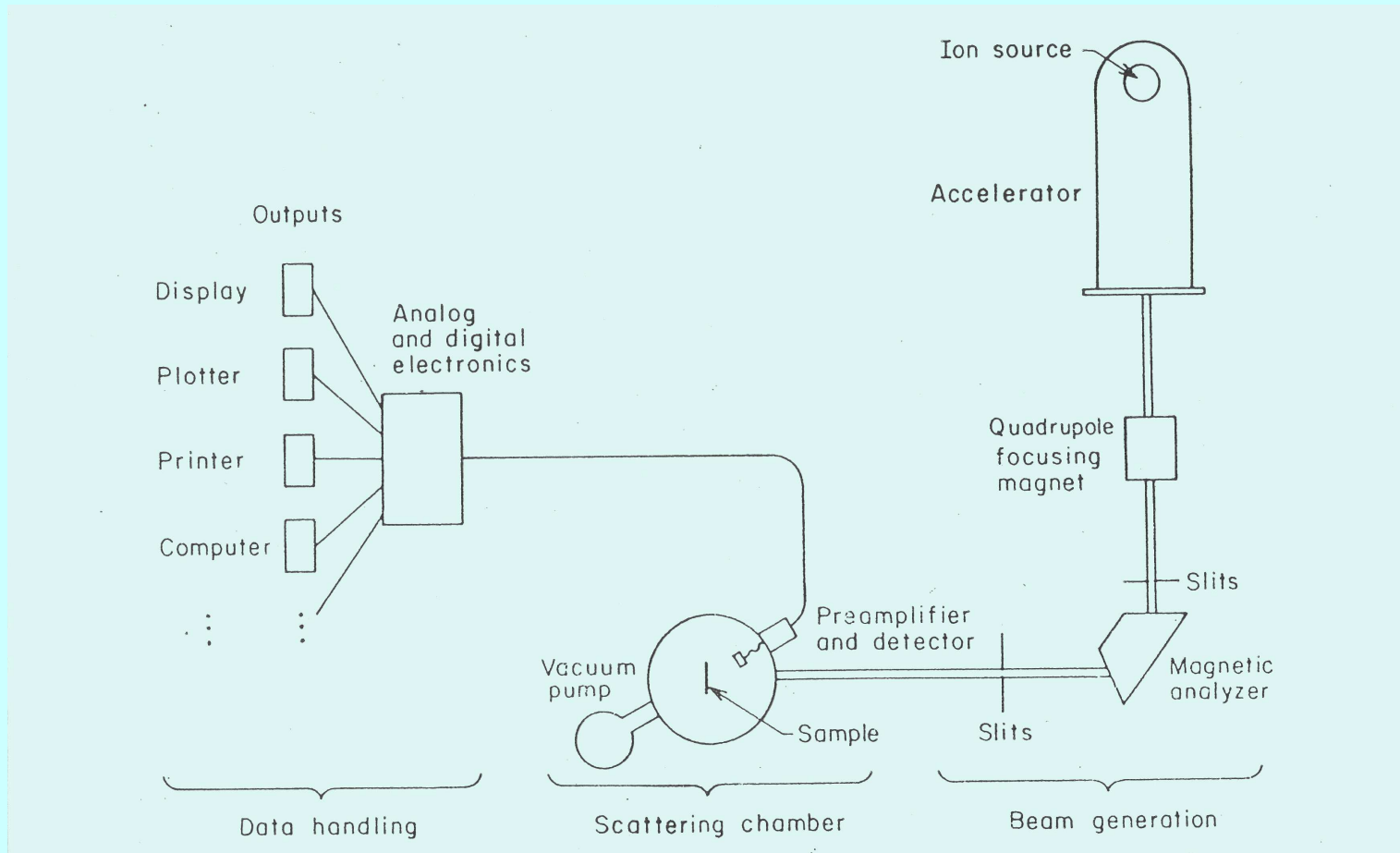


Elastic scattering of light ions on the Coulomb potential of the atomic nuclei.

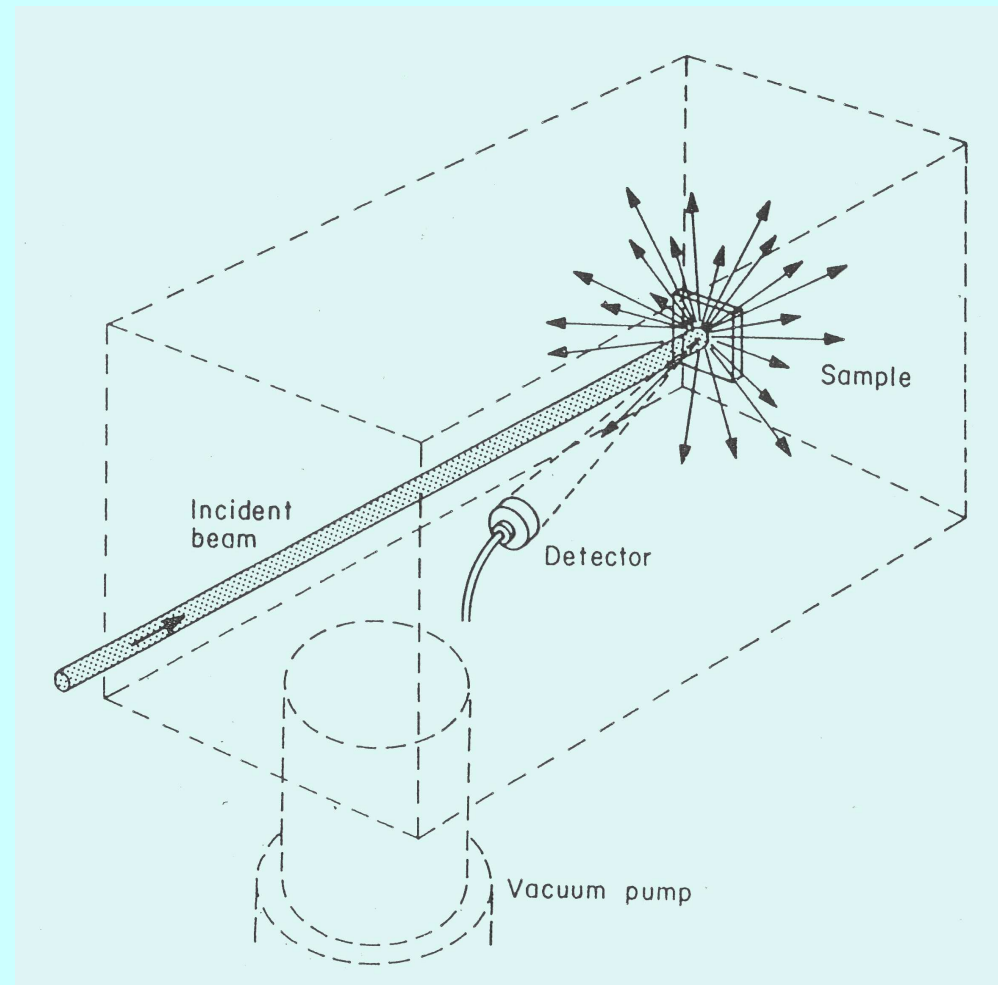
First RBS measurement has been performed by Geiger und Marsden in 1913 in order to prove the new scattering theory of Rutherford.

First application:
analysis of the moon surface during the Surveyor V. mission in 1967 (Turkevich 1968), using the 6.1 MeV α -particles of a ^{242}Cm -Quelle

Diagrammatic set-up of the RBS measurements



simplified view of a scattering chamber



If the impact factor (distance between projectile and nucleus) is small enough, α - particles will be backscattered.

Because of the small impact factor the repulsive Coulomb potential is very strong ($F_c \sim 1/r^2$).

The energy of the backscattered particles will be determined by the kinematic factor:

$$K = E_1/E_0$$

with $E_0 = 1 \text{ MeV}$:

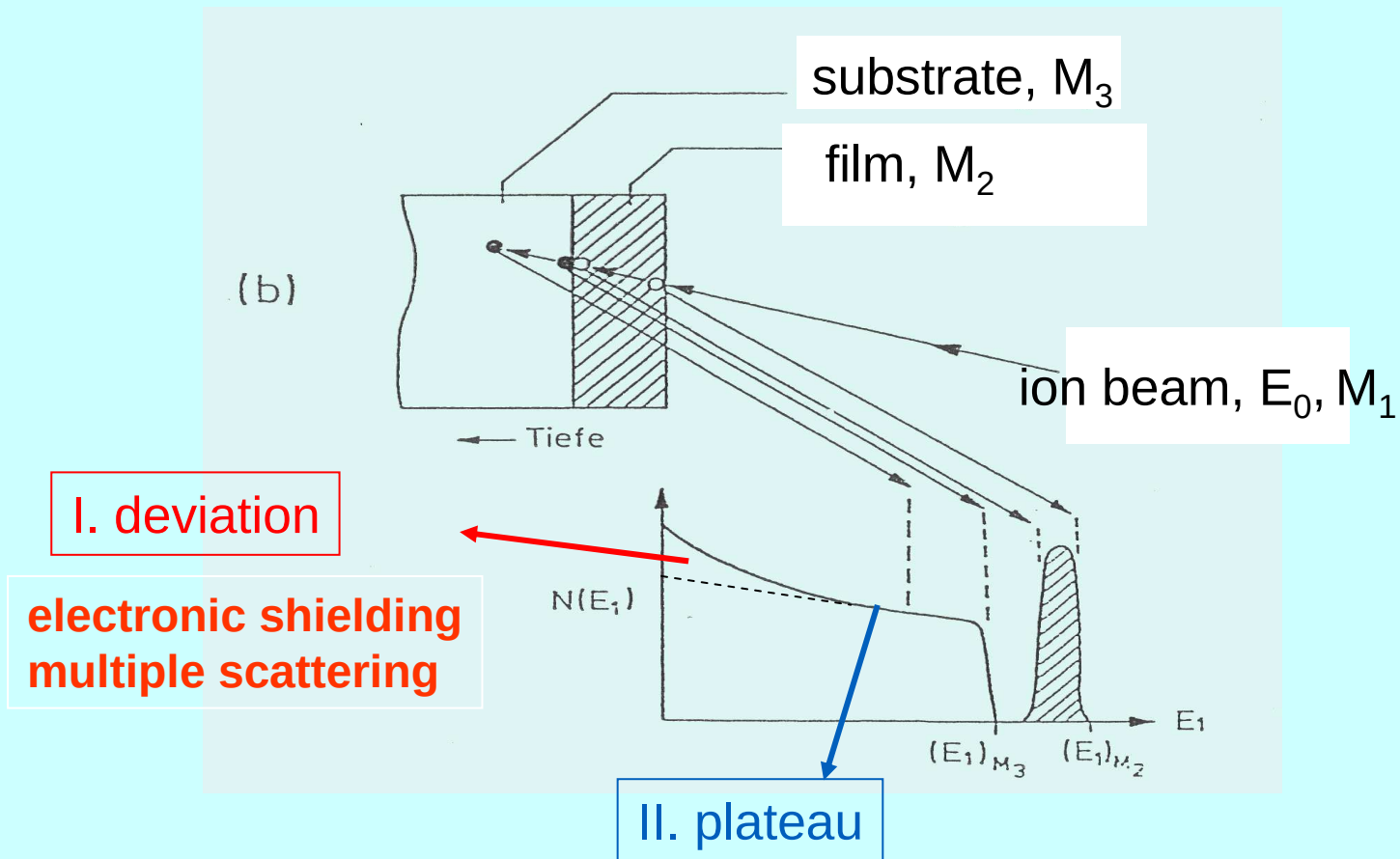
$$K(\text{Al}) = 0.5527$$

$$E_1(\text{Al}) = 552.7 \text{ keV}$$

$$K(\text{Au}) = 0.9225$$

$$E_1(\text{Au}) = 922.5 \text{ keV}$$

RBS spectrum of a film-on-substrate sample

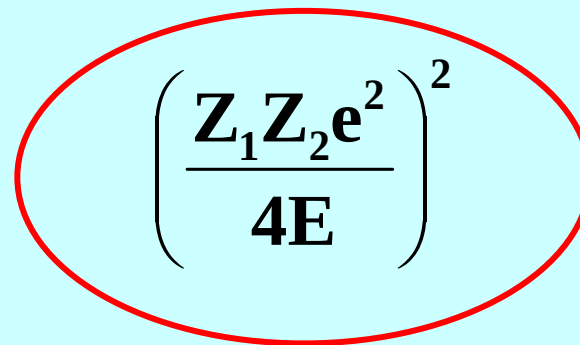


$$\sigma_R \approx \frac{1}{E^2}$$

The Rutherford cross section

$$\sigma_R = \left(\frac{Z_1 Z_2 e^2}{4E} \right)^2 \frac{4}{\sin^4 \Theta} \frac{\left\{ \left[1 - \left(\frac{m}{M} \sin \Theta \right)^2 \right]^{1/2} + \cos \Theta \right\}^2}{\left[1 - \left(\frac{m}{M} \sin \Theta \right)^2 \right]^{1/2}}$$

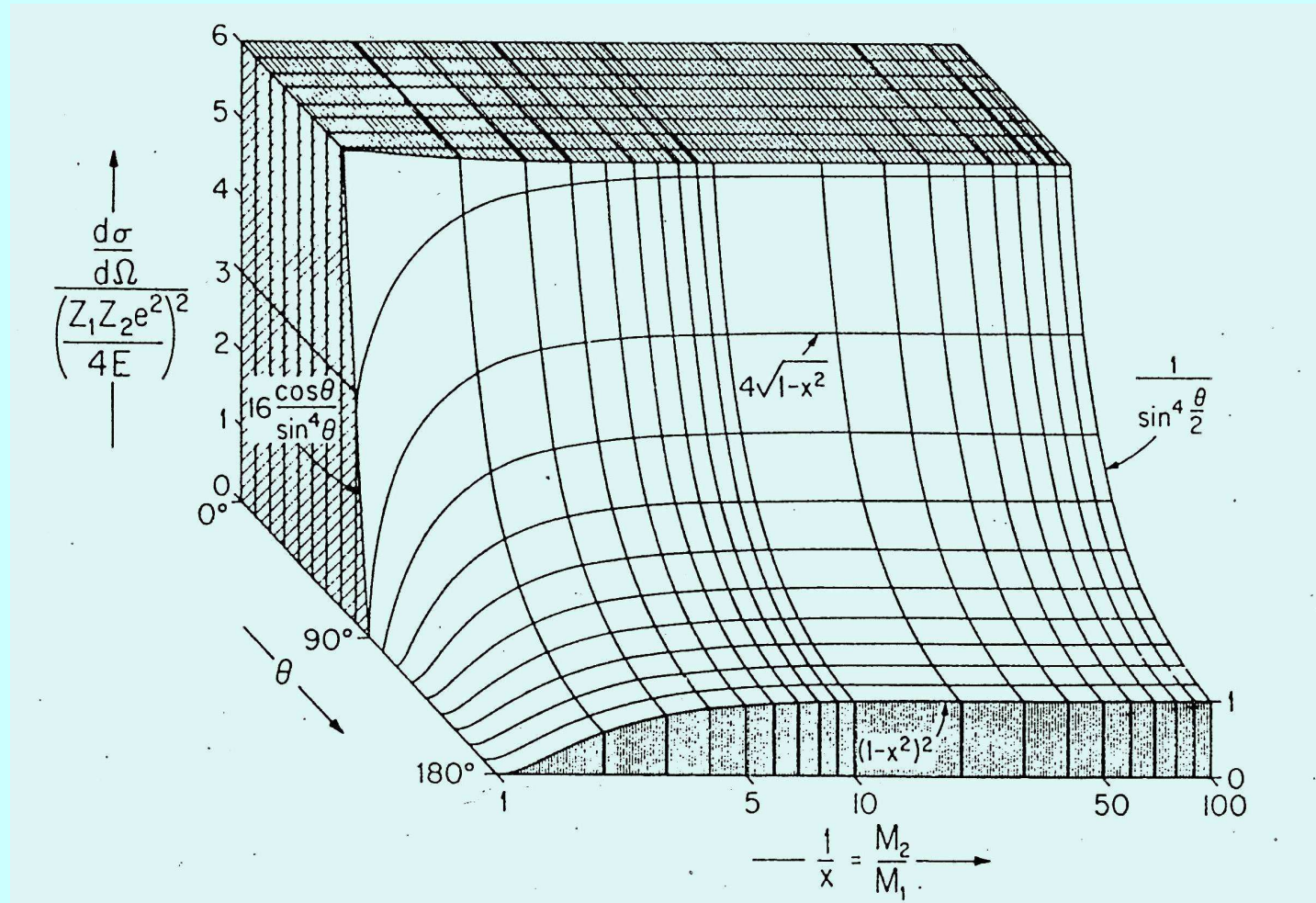
Most important is the pre-factor:


$$\left(\frac{Z_1 Z_2 e^2}{4E} \right)^2$$

The Rutherford cross section depends on the:
pre-faktor
mass ratio (m/M)
scattering angle (Θ)

$$\frac{\sigma_R}{\left(\frac{Z_1 Z_2 e^2}{4E}\right)^2} \approx \frac{m}{M}, \Theta$$

The dependence of the Rutherford differential scattering cross section as a function of the scattering angle θ and the mass ratio $x^{-1} = M_2/M_1$



Intensity (counts in the RBS spectrum) is:

$$A = Q N t \sigma_R \Omega$$

Q – charge; σ_R – Rutherford cross section; Ω – detector solid angle
If they are known $\longrightarrow$ Nt (mass density) is to define

This has the consequence that:

1. If the layer thickness is known, density can be determined
2. If the density is known, thickness can be determined

Mass sensitivity

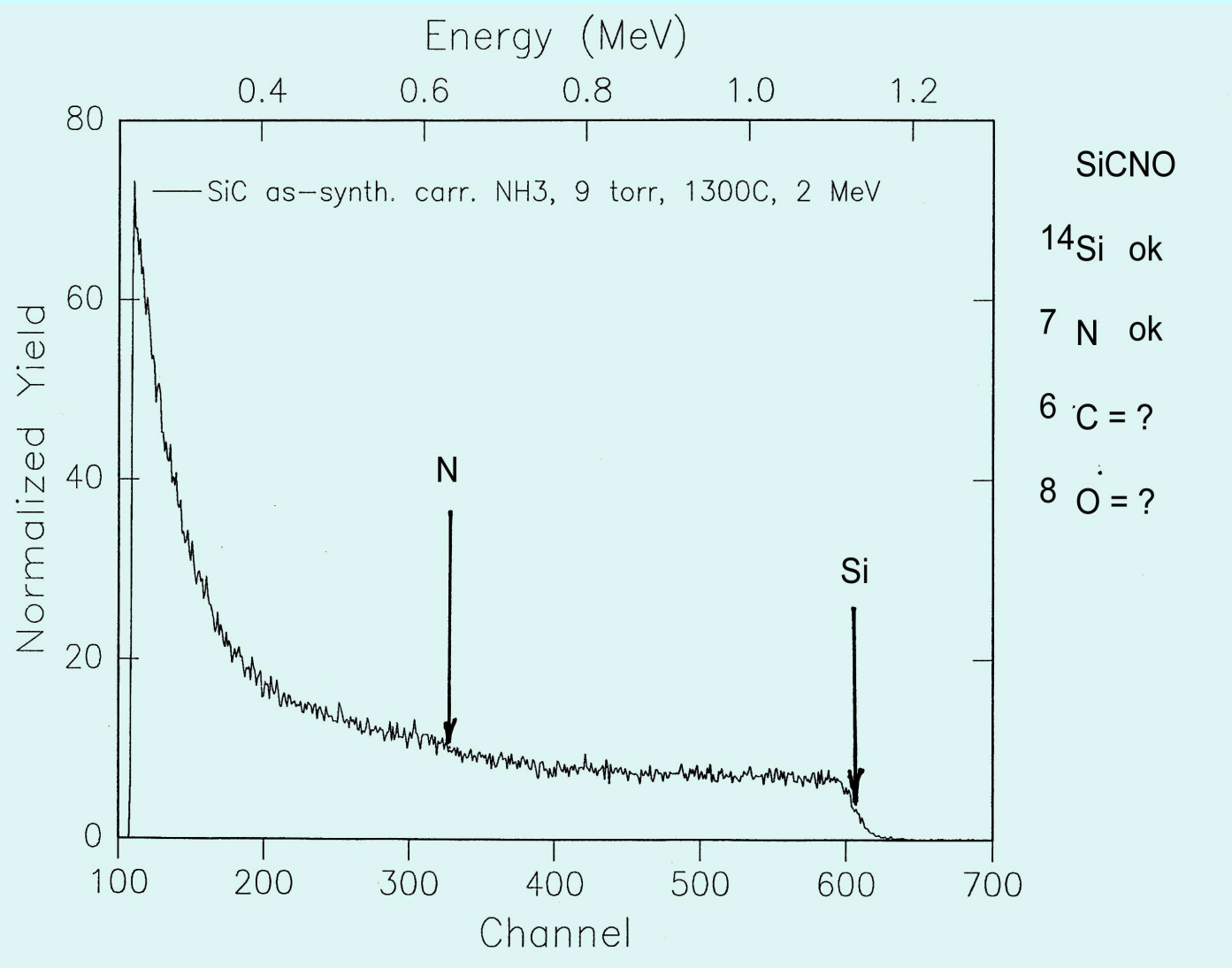
To get a high mass sensitivity it is necessary that ΔM gives rise to a high ΔE_1 :

$$\Delta E_1 = E_0 (4 - \delta^2) \left(\frac{m}{M^2} \right) \Delta M$$

possibilities:

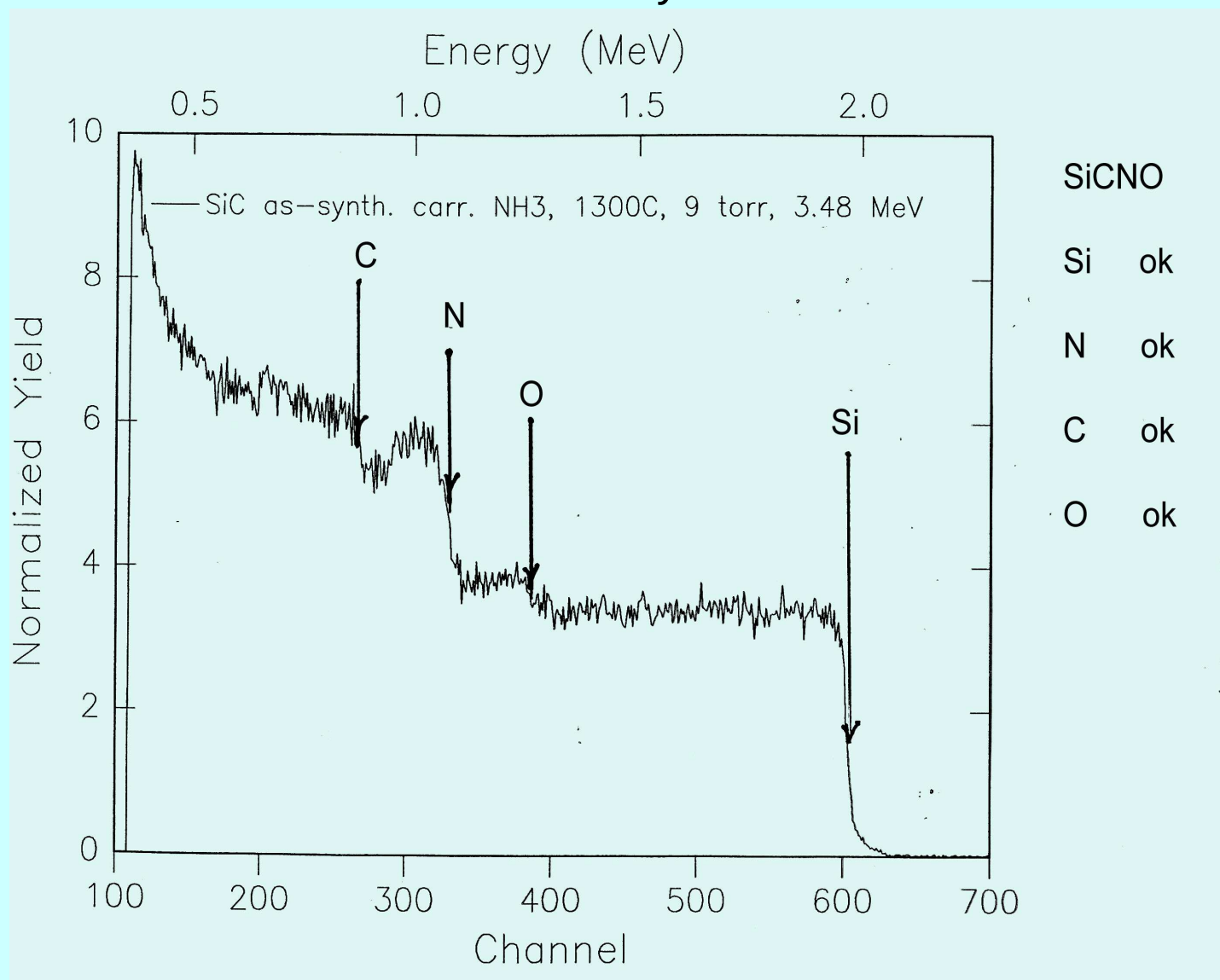
- high primary energy
- heavy primary ion
- high scattering angle

Light element sensitivity at E=2 MeV

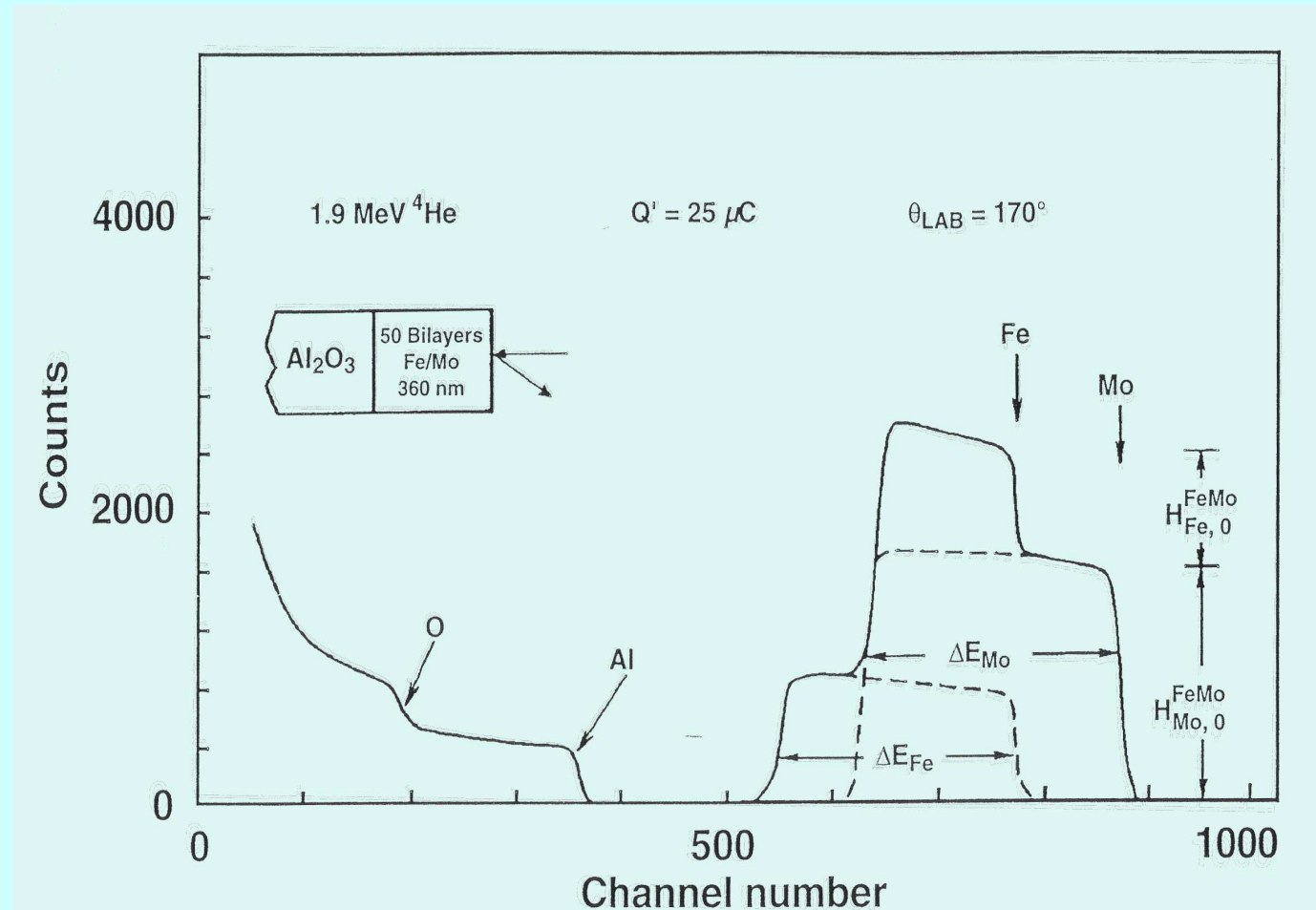




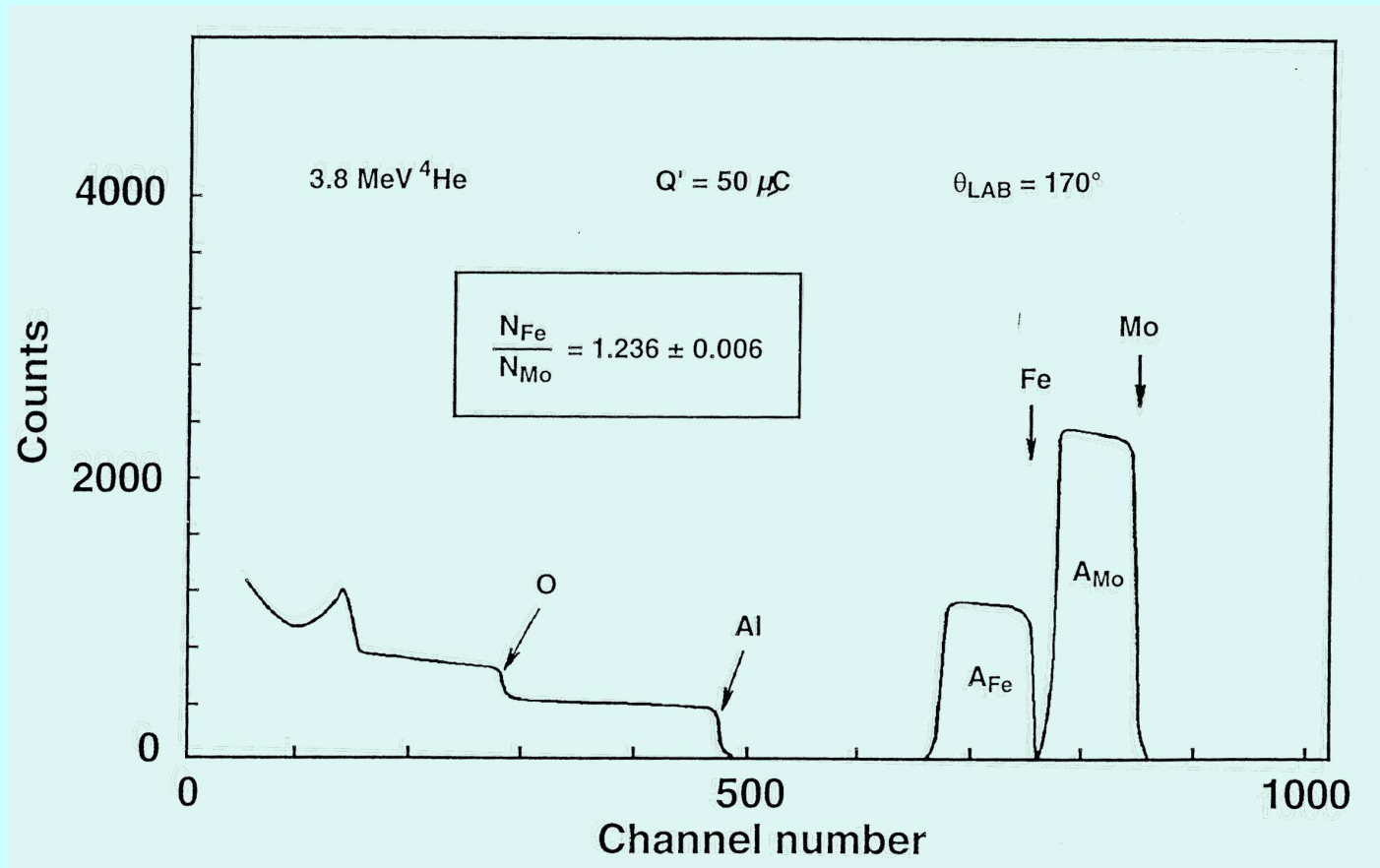
Increased sensitivity at 3.5 MeV



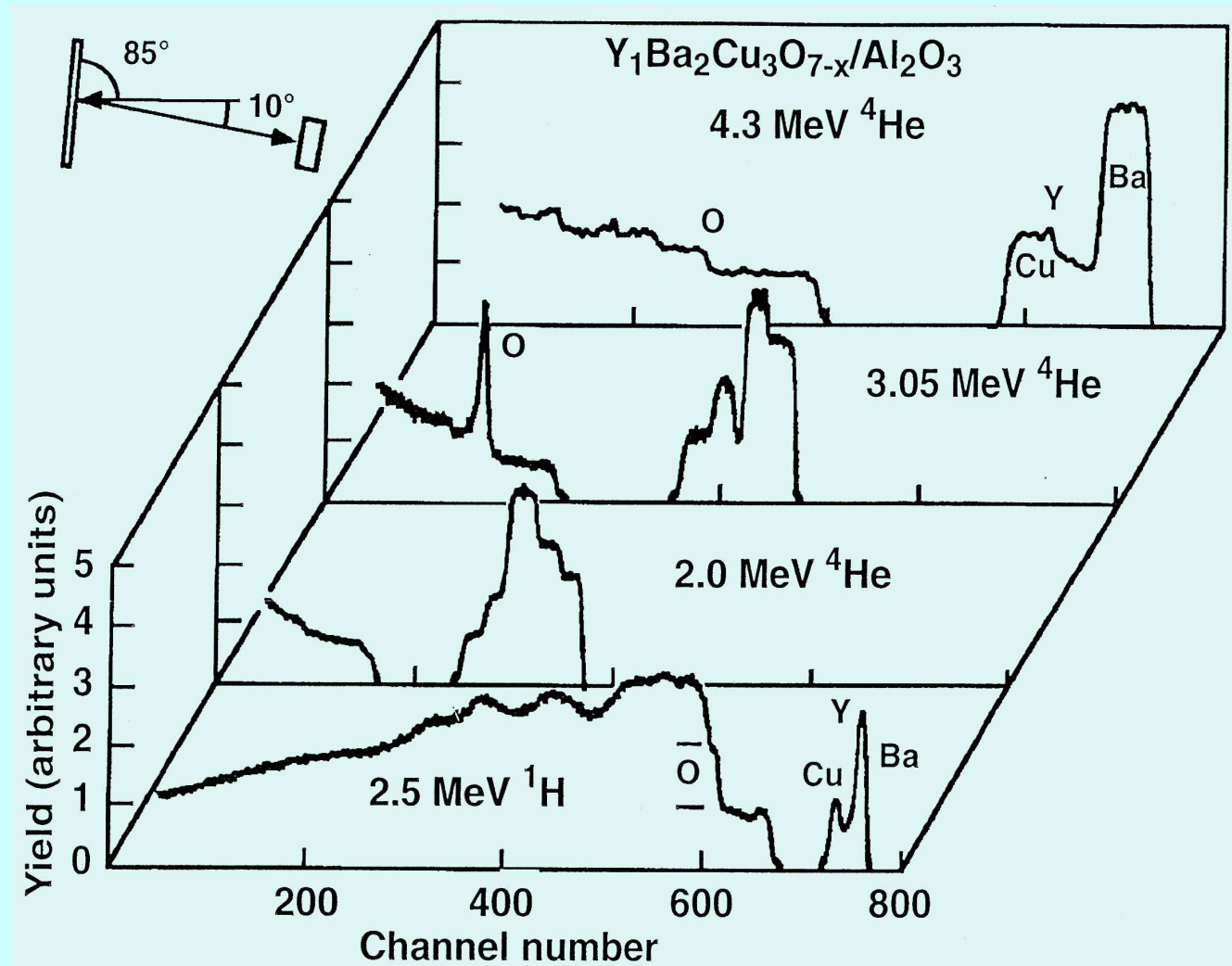
Resolution of thin Fe/Mo multilayers with 1.9 MeV He ions



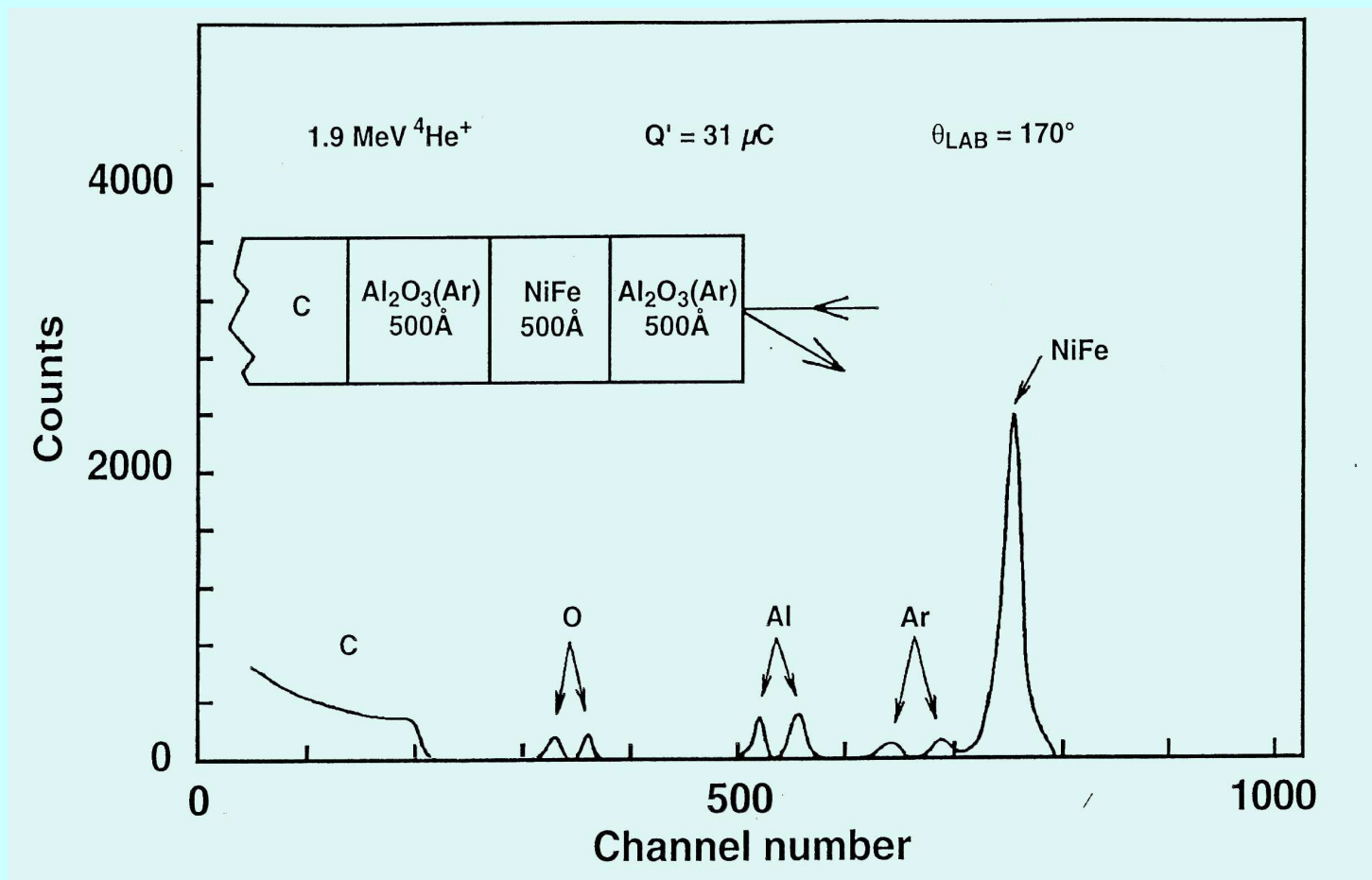
Increased resolution using 3.8 MeV He ions



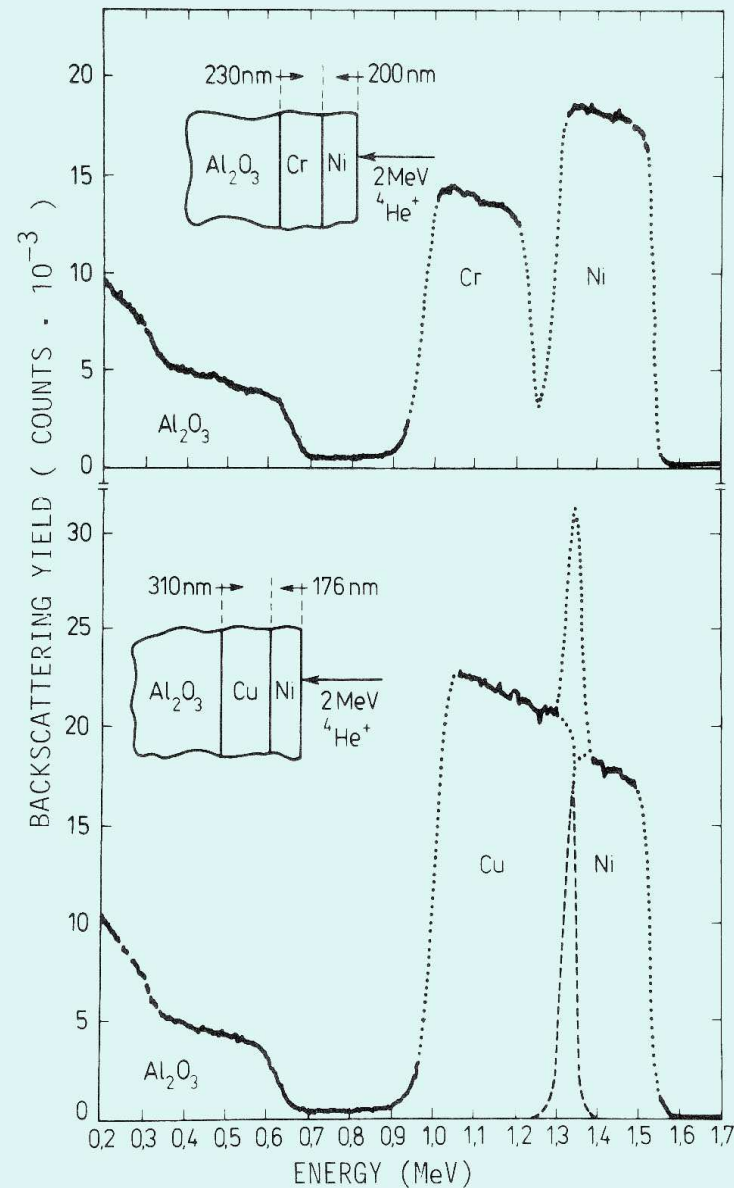
Dependence of
the RBS spectrum
of a high-Tc
superconductor
on the energy and
on the primary
ions



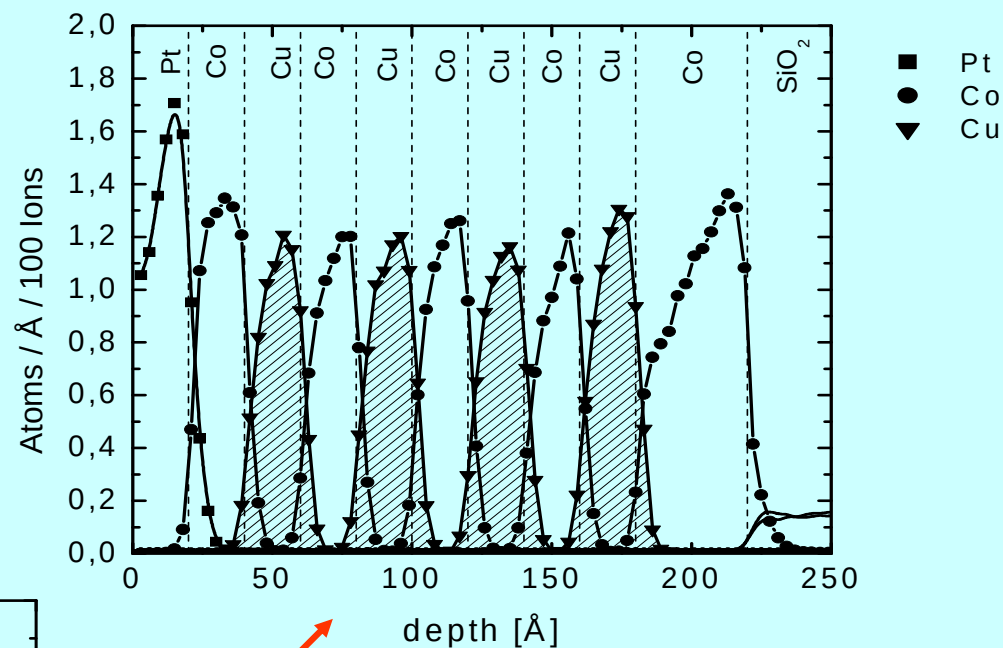
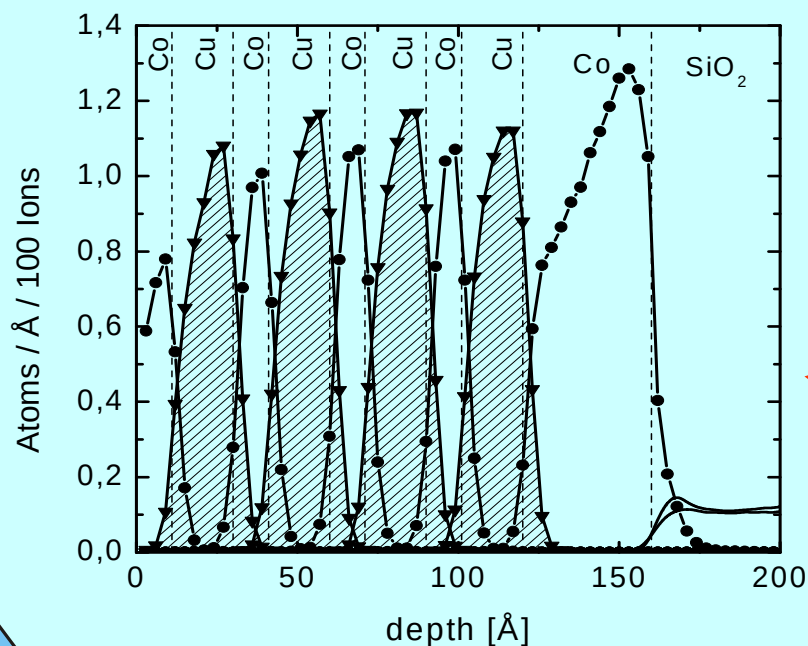
It is to be noted that the geometry of the sample does not fit the order of the peaks in the RBS spectrum



RBS spectra from metal layers on Al_2O_3 substrates



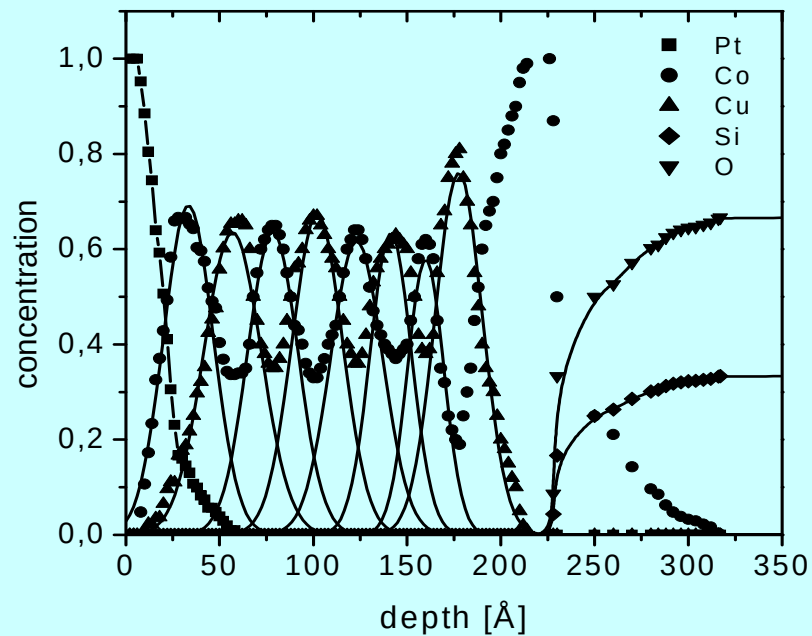
Distribution of recoil atoms by Monte-Carlo (TRIM) simulation for two GMR thin film systems



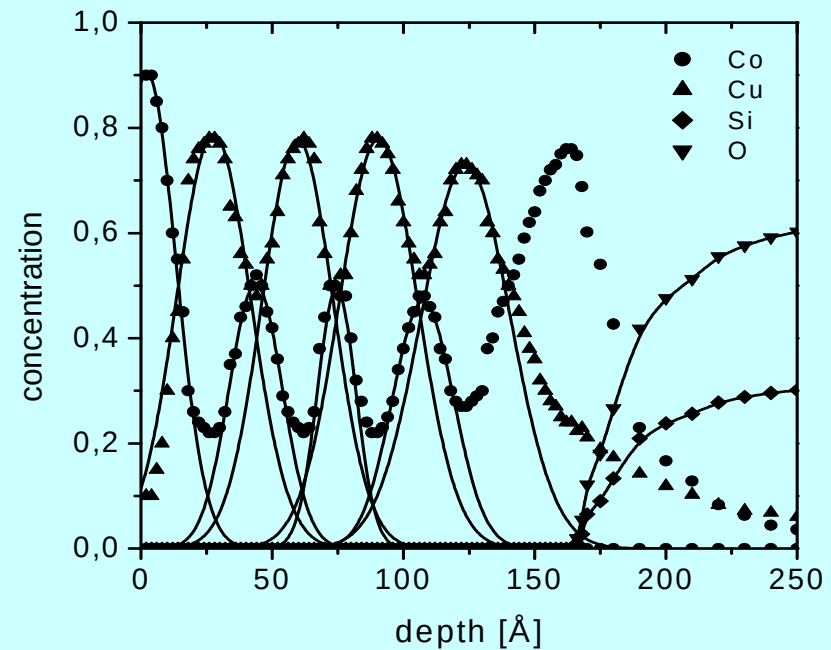
Pt(2nm)/[Co(2nm)/Cu(2nm)]₄/Co(4nm)/SiO₂

[Co(1.1nm)/Cu(1.9nm)]₄/Co(4nm)/SiO₂

RBS measurements with nanometer resolution:
fitted concentration depth profiles.
The Co/Cu layers are strongly intermixed

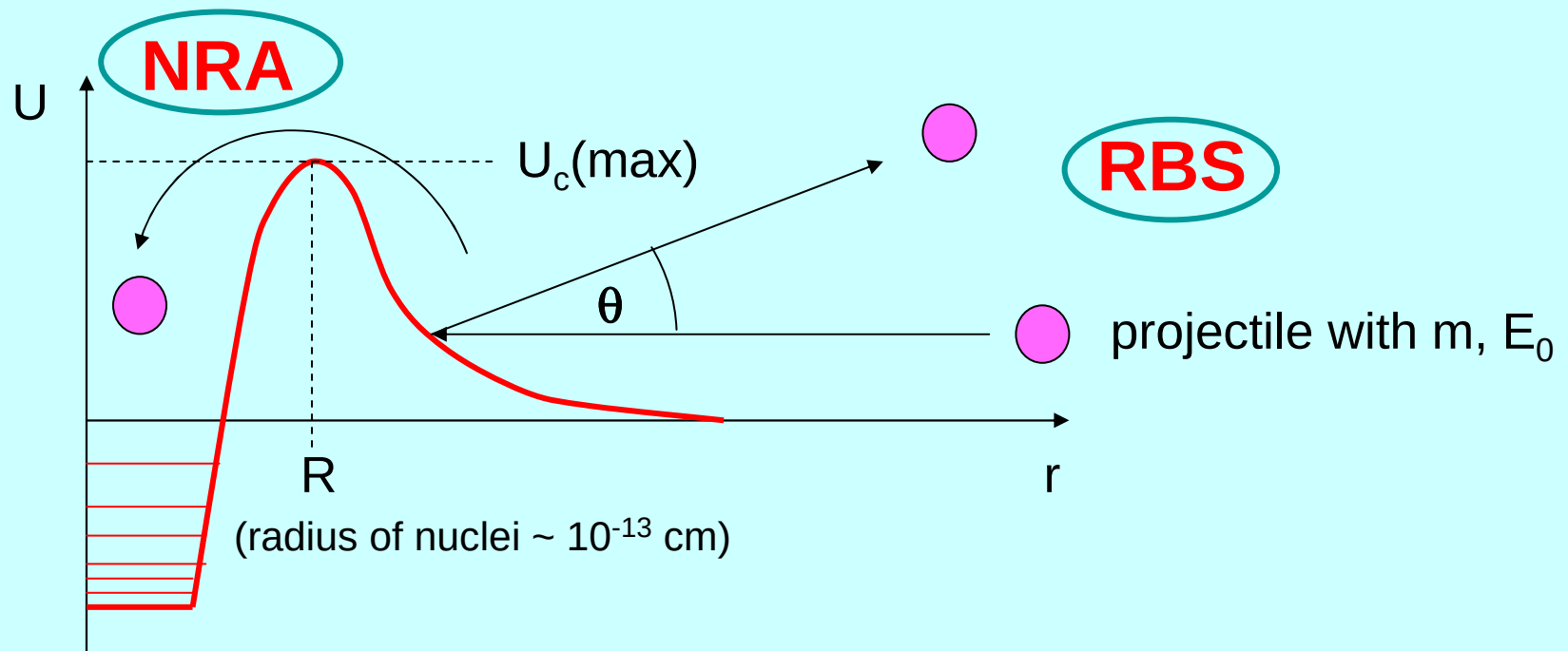


$[\text{Co}(1.1\text{nm})/\text{Cu}(1.9\text{nm})]_4/\text{Co}(4\text{nm})/\text{SiO}_2$



$\text{Pt}(2\text{nm})/[\text{Co}(2\text{nm})/\text{Cu}(2\text{nm})]_4/\text{Co}(4\text{nm})/\text{SiO}_2$

RBS vs. NRA



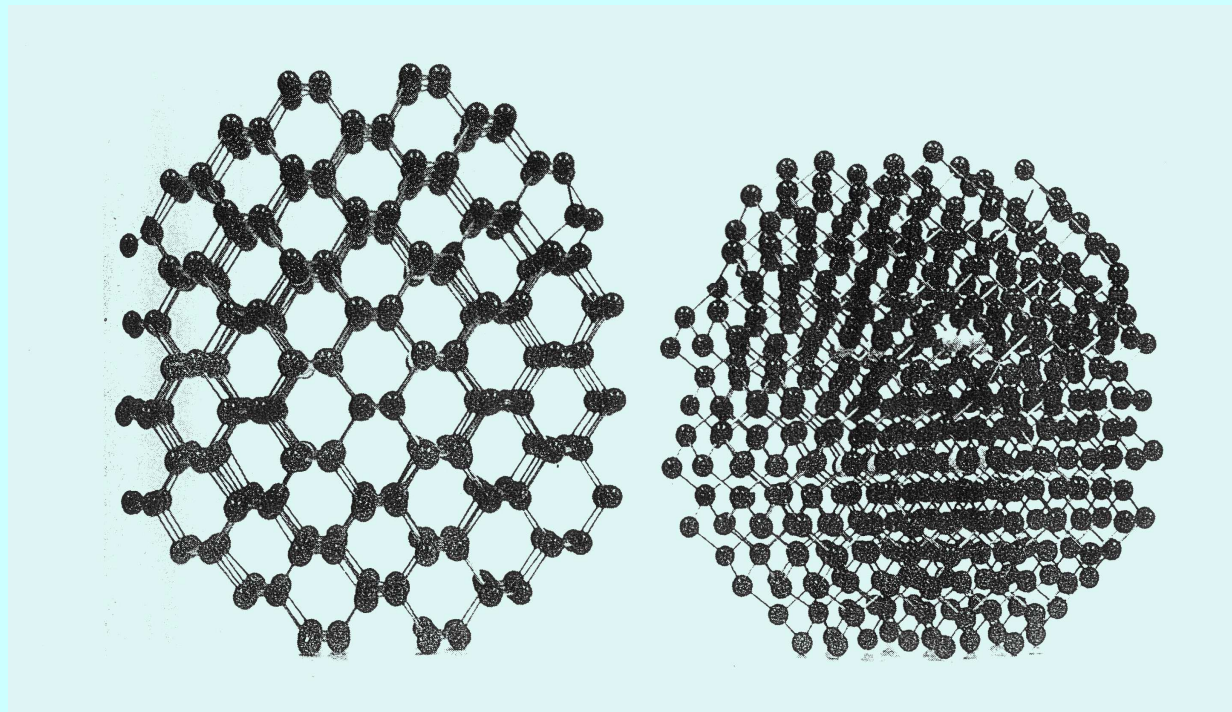
$$U_c(\text{max}) = \frac{Z_1 Z_2 e^2}{R} \approx \frac{Z_1 Z_2 e^2}{A^{1/3}} [\text{MeV}]$$

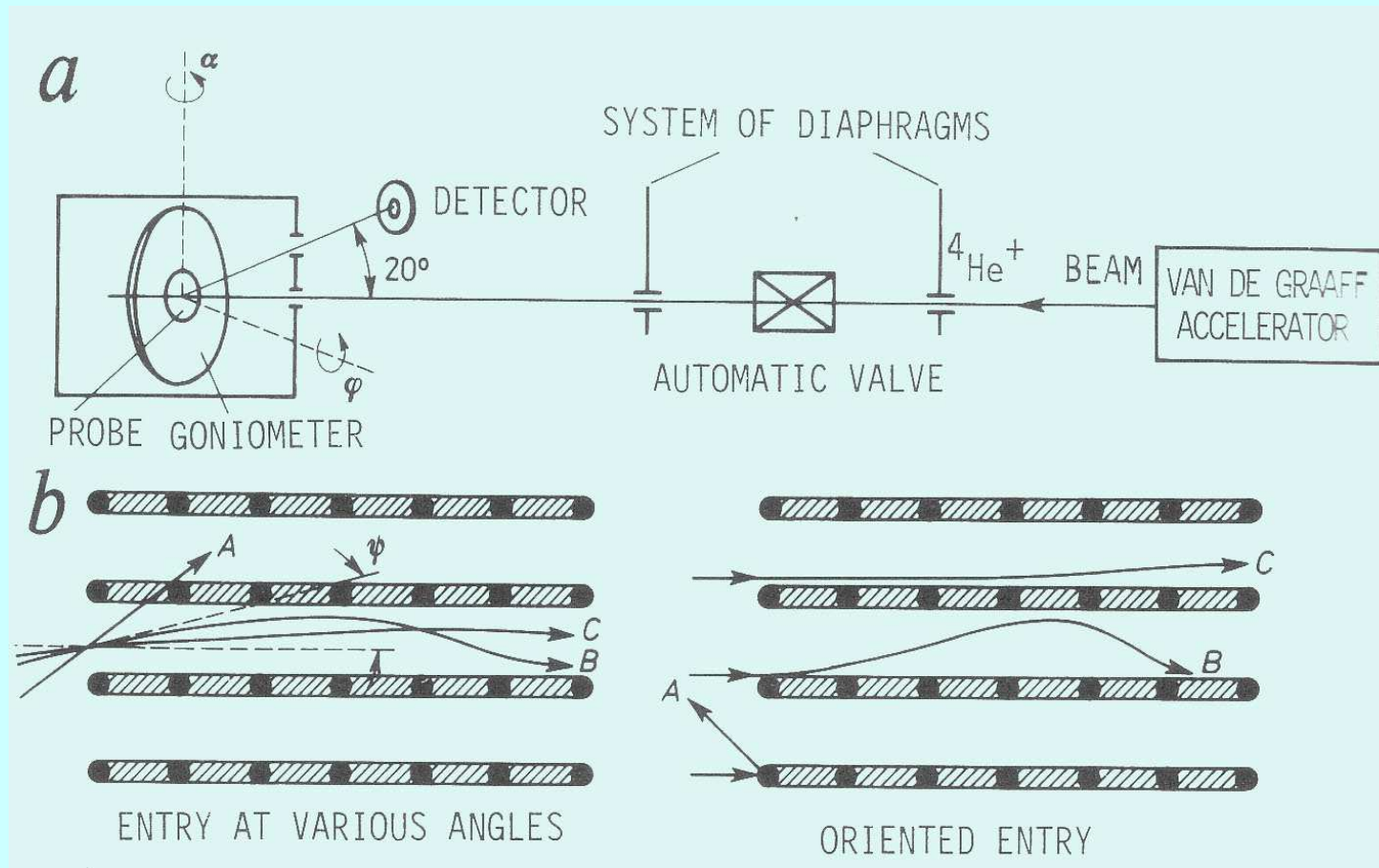


Channeling



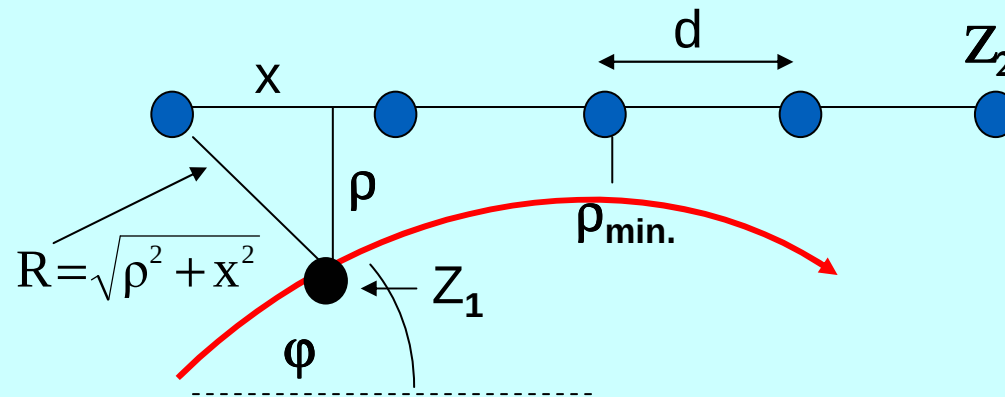
Crystall lattice from Channeling (aligned) and RBS (random) view





RBS measurements using the channeling effect:
 (a) lay-out of the apparatus,
 (b) principle of the channeling effect

Trace of an ion with angle φ in a lattice channel



continuum modell of Lindhard:

atoms are equally charged;

the wall potential has the average value of the atomic potentials

According the theory of Lindhard is the potential:

$$U(\rho) = \frac{1}{d} \int V(R) dx$$

$V(R)$ is the atomic potential (e.g. Thomas-Fermi potential)

The critical angle is:

$$\varphi_c = \left[\frac{U(\rho_{\min})}{E} \right]^{\frac{1}{2}}$$

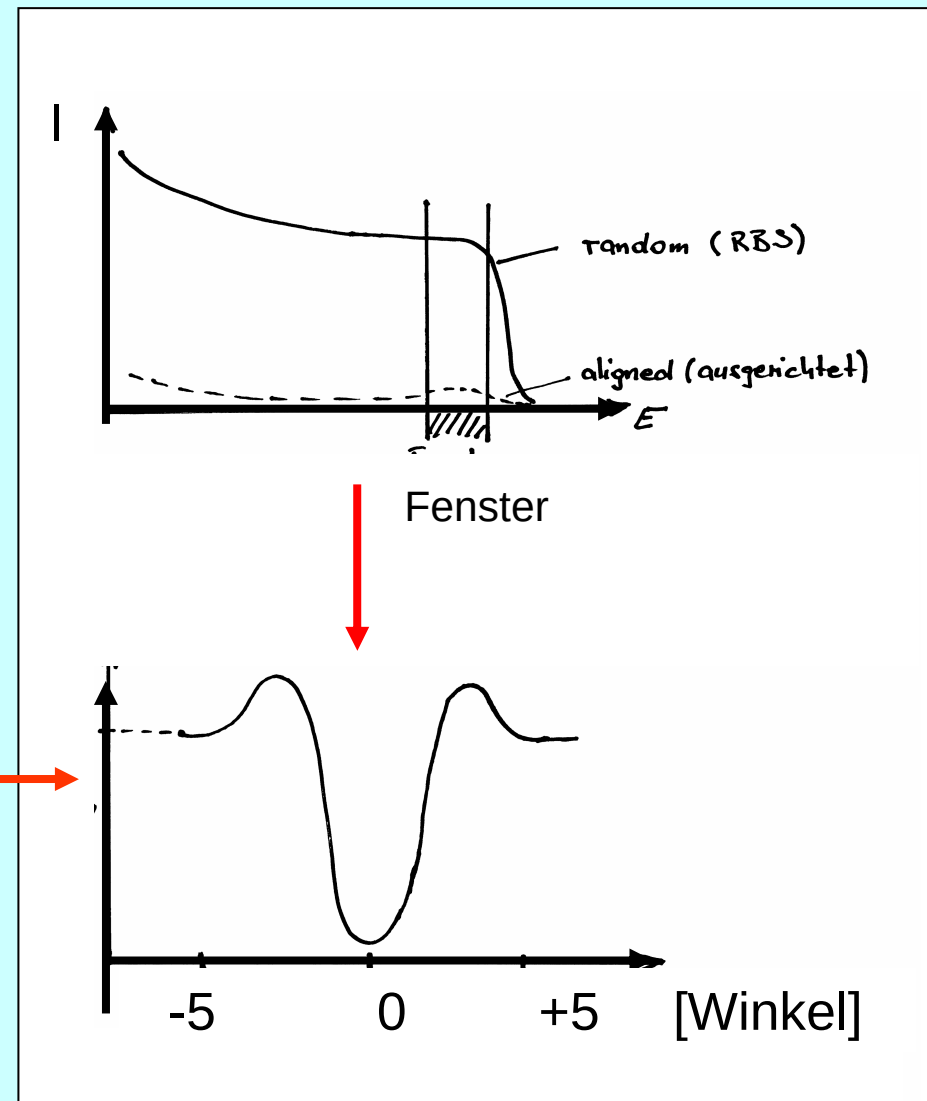
or as an approach:

$$\varphi_c = \left(\frac{2Z_1 Z_2 e^2}{Ed} \right)^{\frac{1}{2}}$$

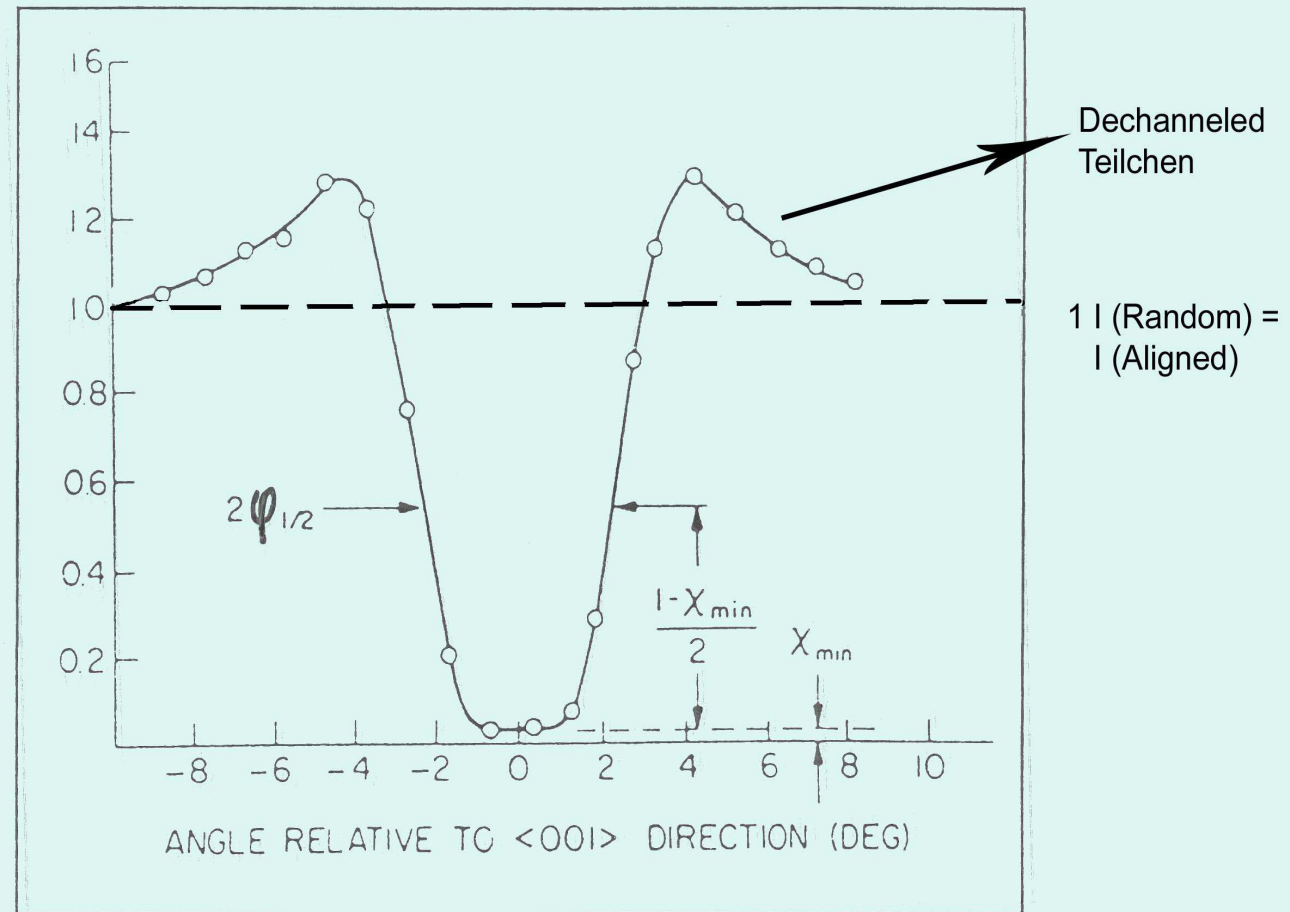
for typical RBS measurements with 1-2 MeV He^+ ions it has the value of about 1°

Dependence of the channeling spectrum on the angle

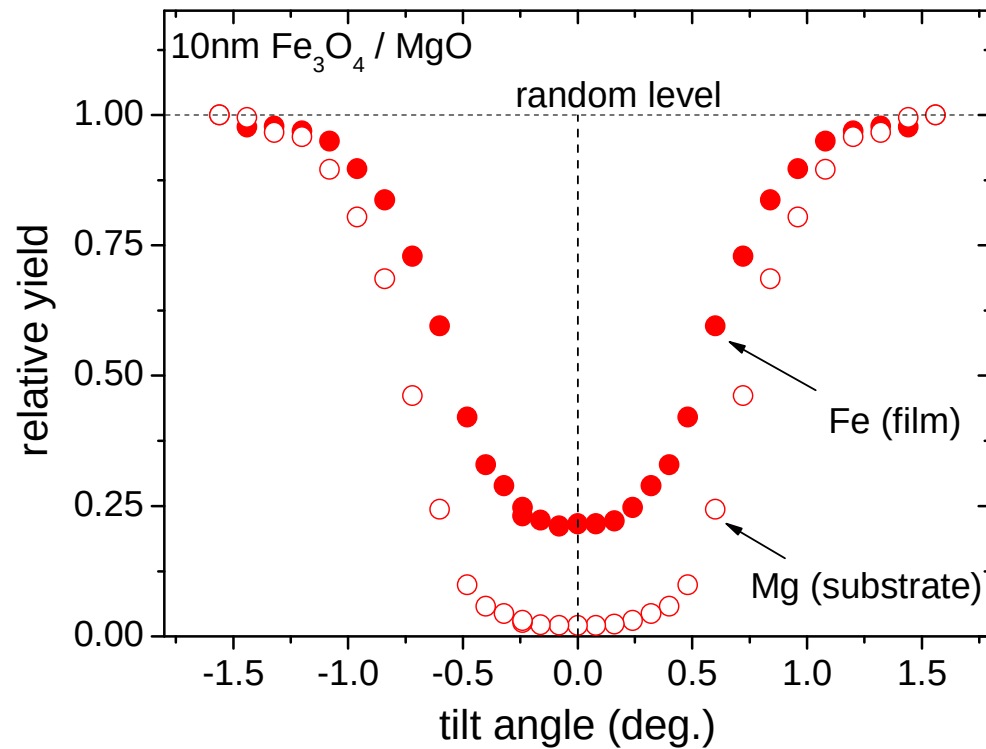
$I(\text{RBS}) / I(\text{aligned})$



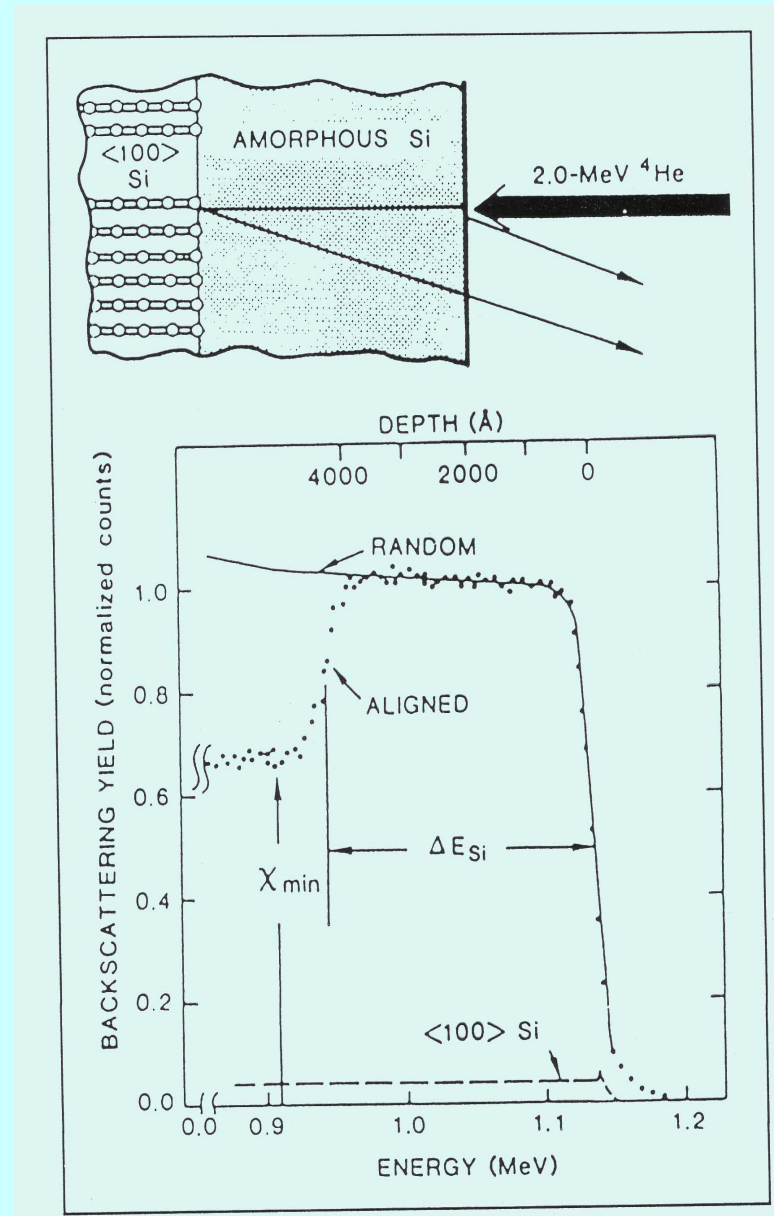
Channeling differential curves



Channeling curves
of magnetite/MgO
epitaxially grown
layers.



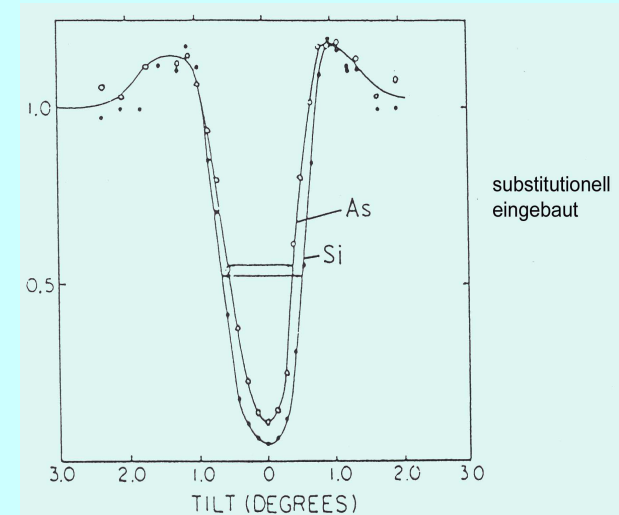
Random and aligned spectra of an a-Si/c-Si sample



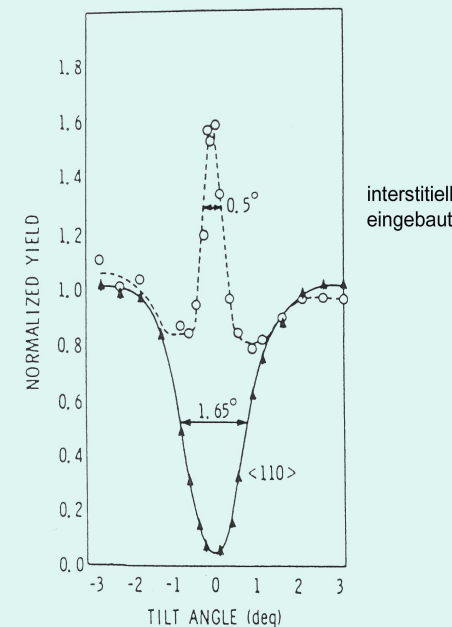
Implantation into Si

The implanted As is on a substitutional lattice place

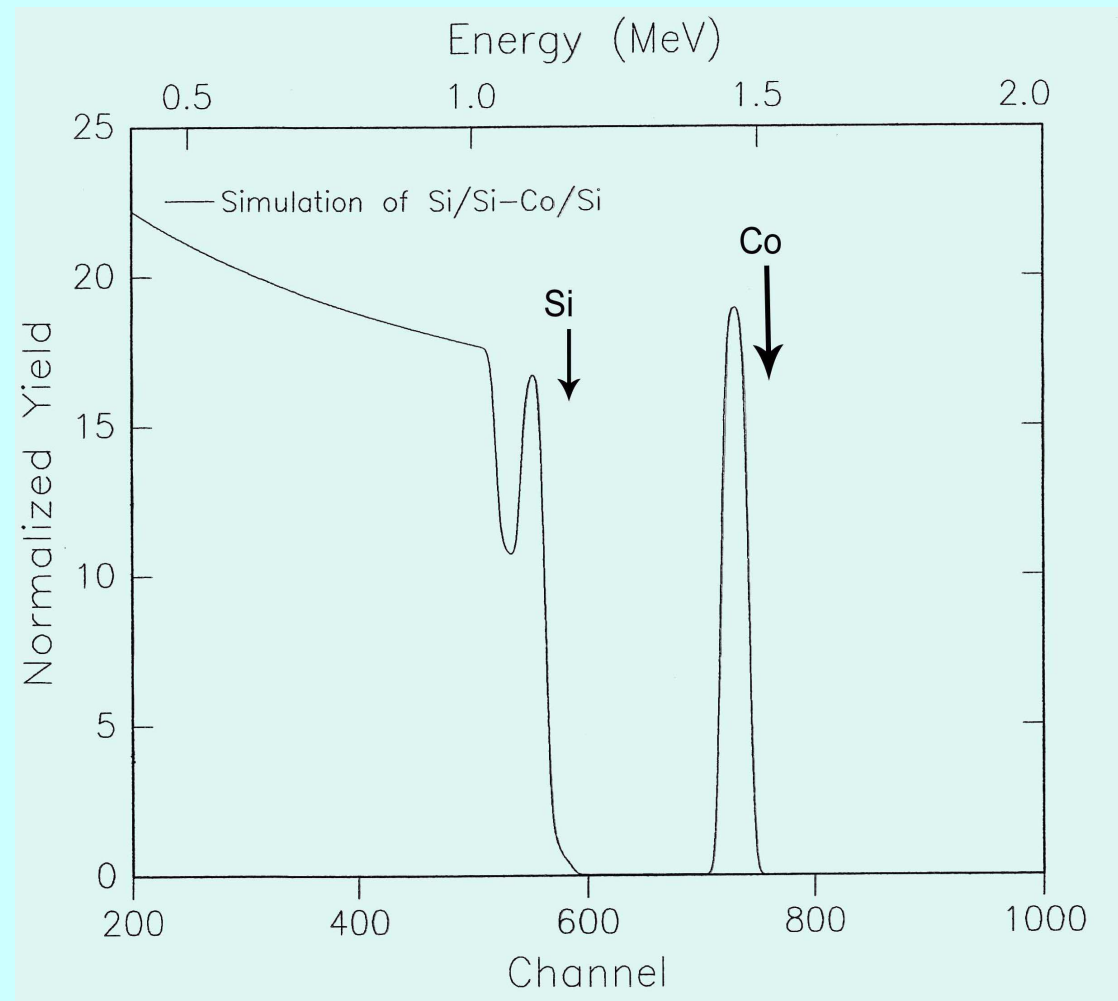
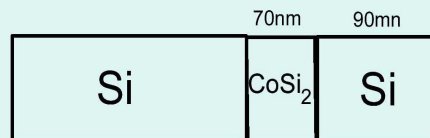
The implanted Yb is on an interstitial lattice place („flux peaking effect“ at the centre of a channel)



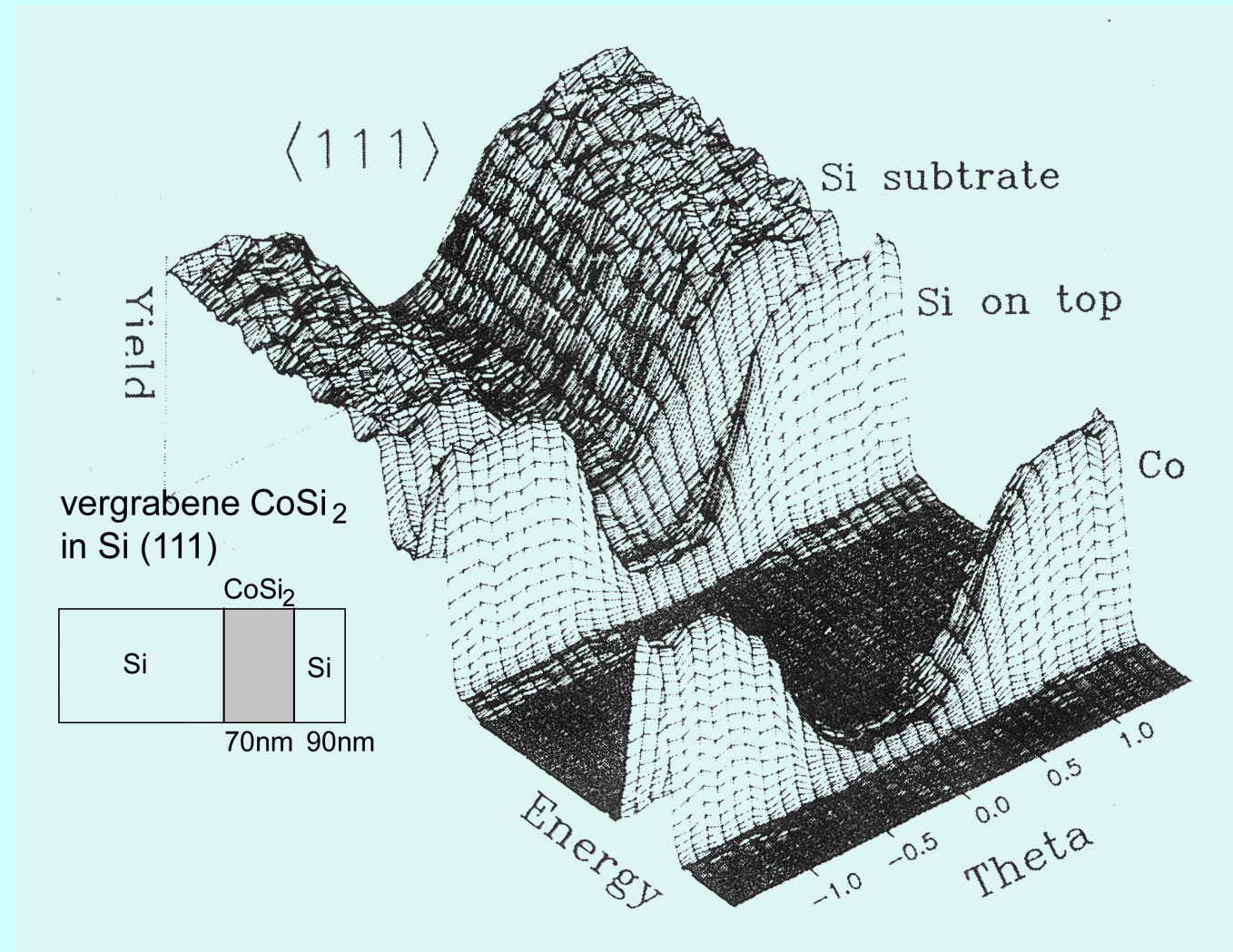
As in Si



RBS spectrum of a buried CoSi_2 -layer

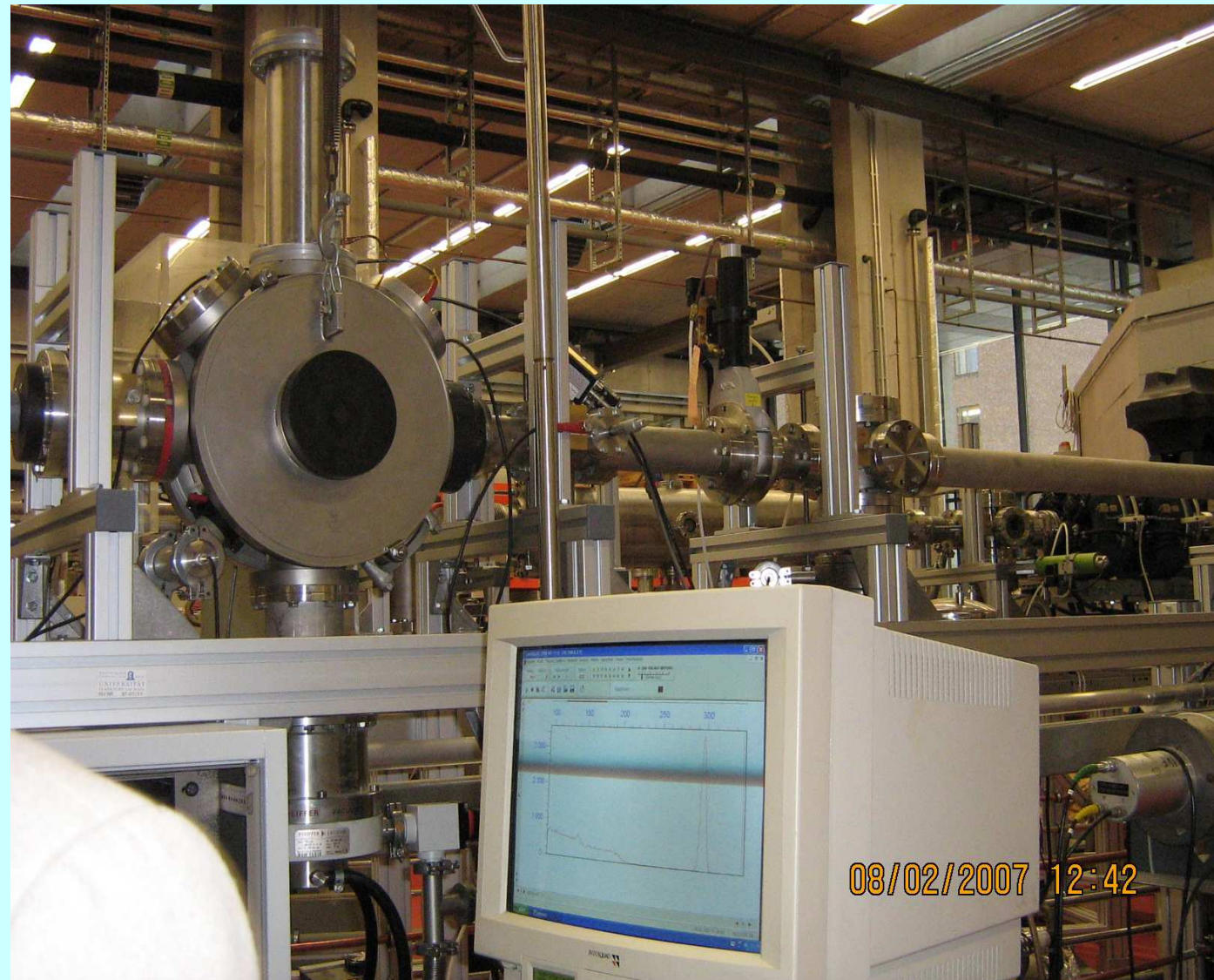


3D-spectrum of the buried silicide layer



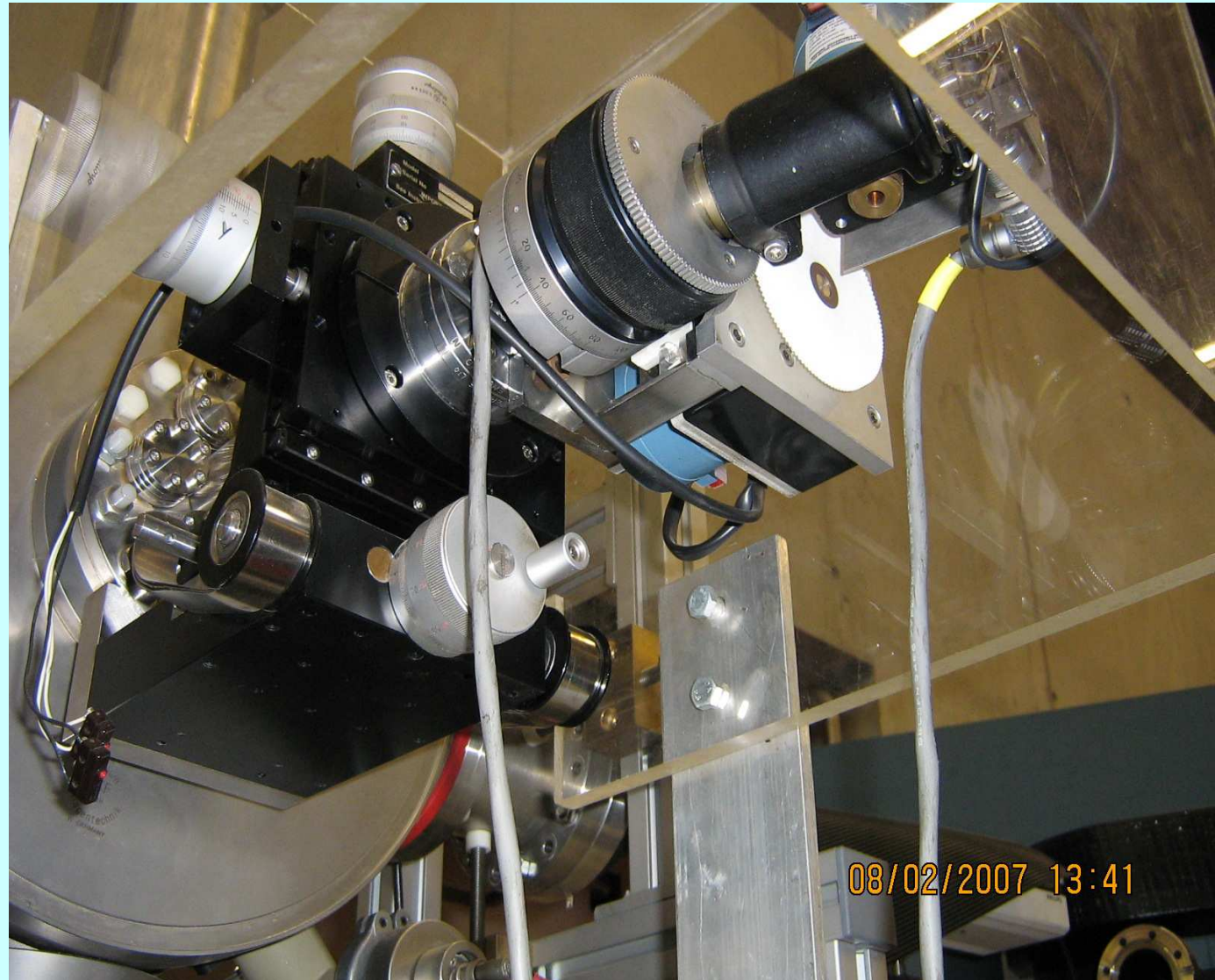


Channeling set-up in the Institut für Kernphysik, Uni Frankfurt



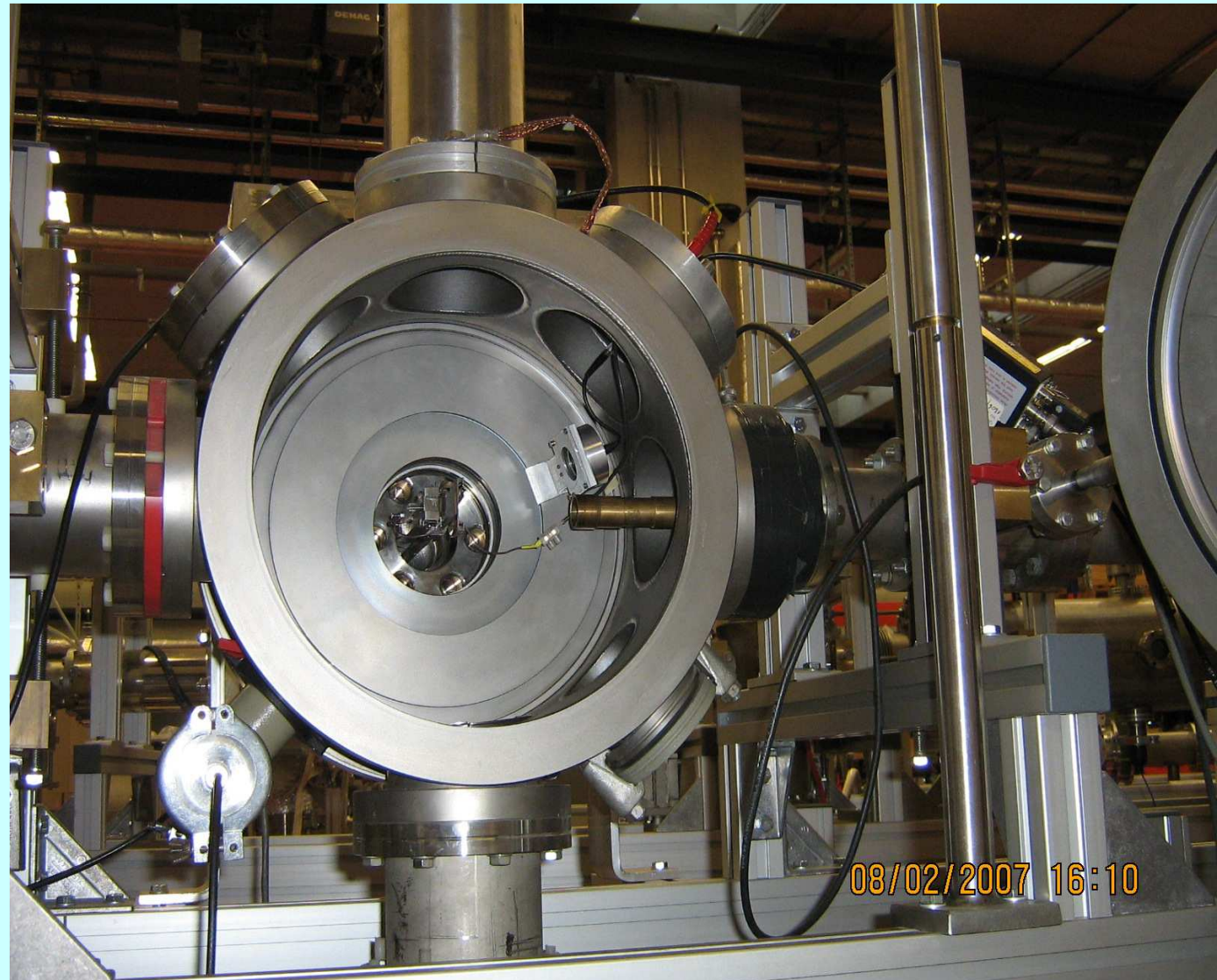


Stepping Motor and Goniometer





Scattering chamber with detector



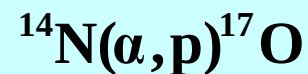


Nuclear Reaction Analysis (NRA)



First nuclear reactions that have been performed:

Rutherford, 1919 $\alpha + {}^{14}\text{N} \rightarrow {}^{17}\text{O} + \text{p}$



Cockroft-Walton, in 1932 using 1 MeV protons



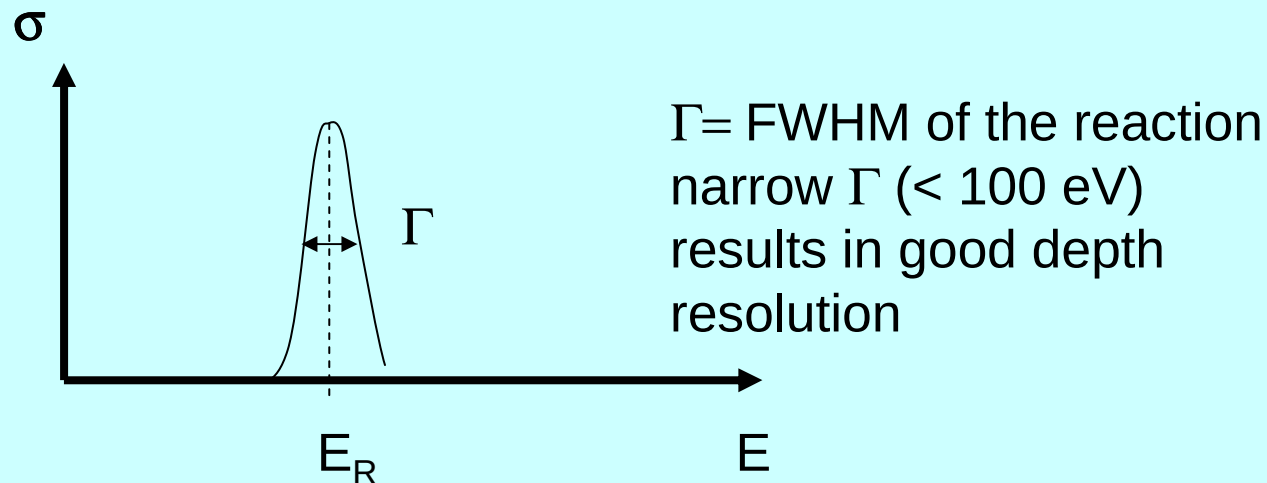
Conservation laws that have to be considered:

- energy
- momentum
- moment of momentum
- charge
- atomic number
- parity

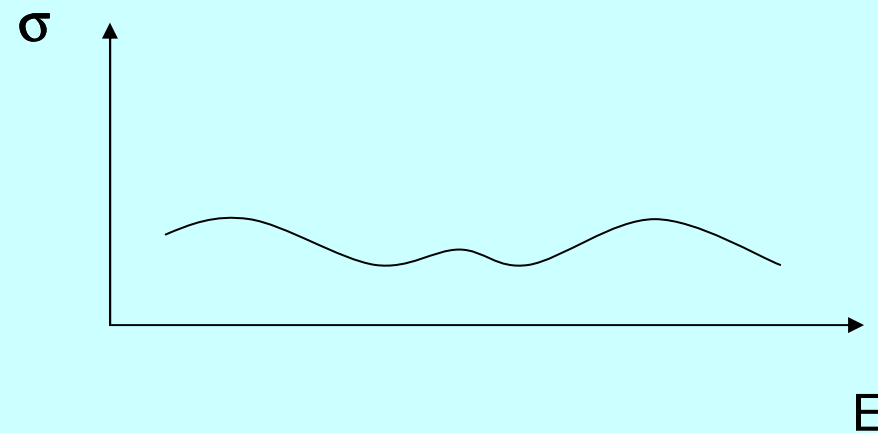


Two kind of nuclear reactions:
resonant and not-resonant

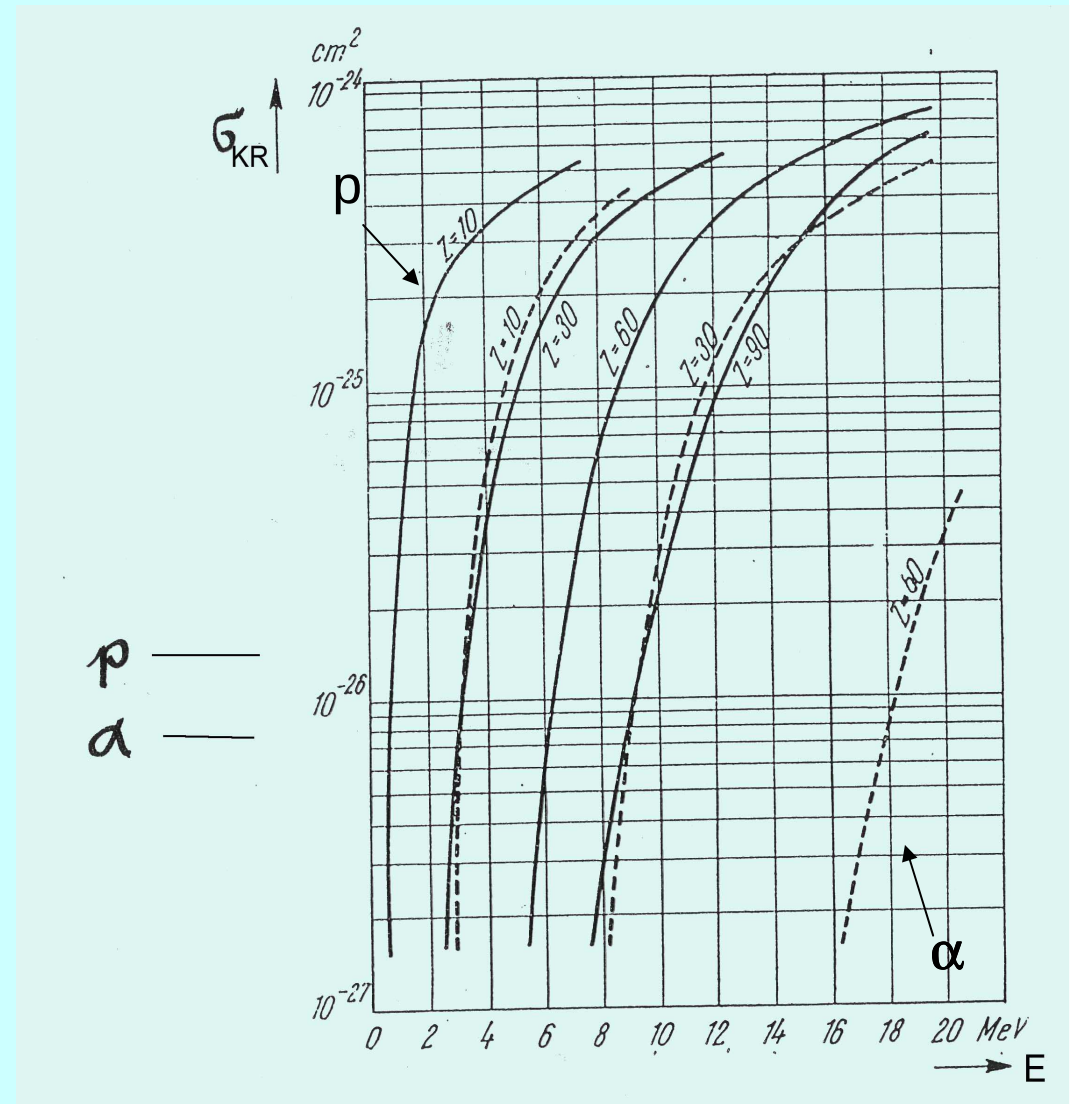
- I. resonant nuclear reactions (requested):
reaction cross section changes strongly with energy (E_R)



II. not-resonant nuclear reaction: cross section changes smoothly with energy



Dependence of cross section on energy for protons and α -particles in different targets



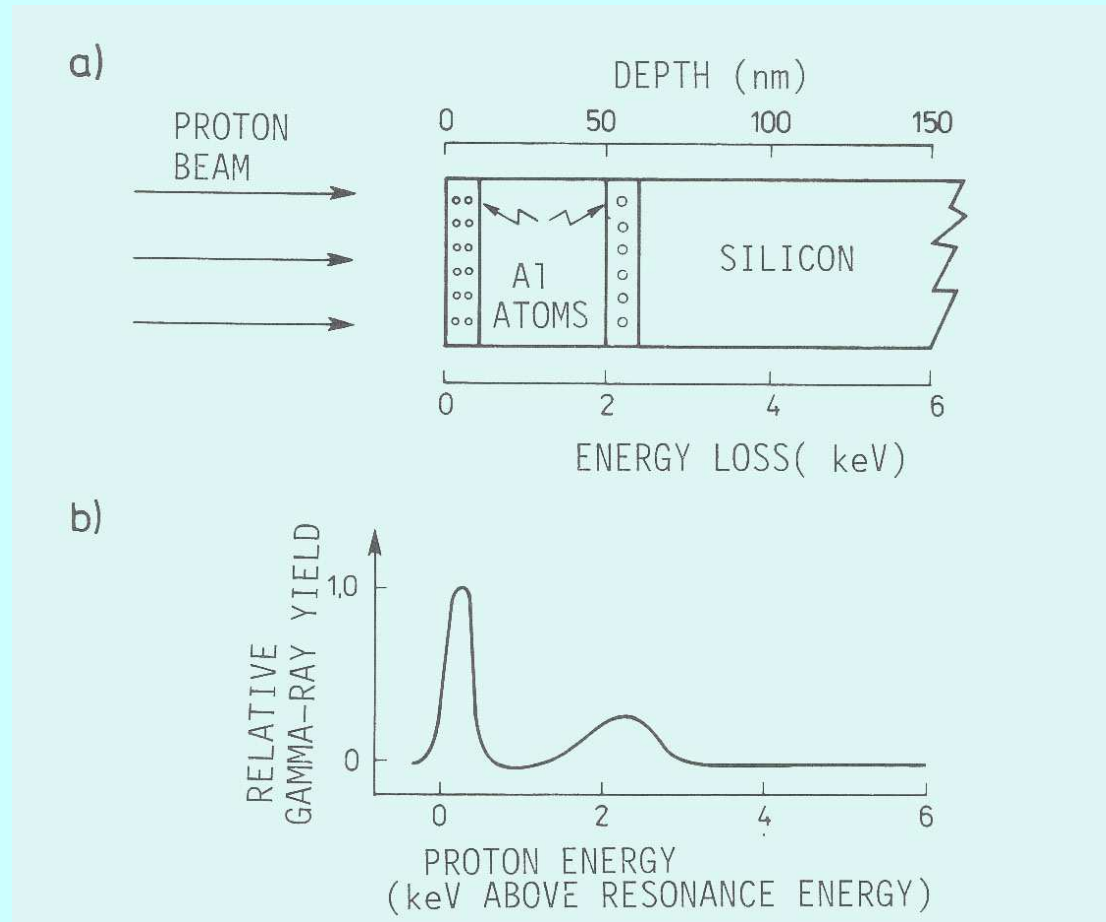


some (p, γ) and (p, $\gamma\alpha$)
reactions in low energy
range between 473 and
675 keV.

special importance has the
(p, γ)- reaction for Al
profiling with a FWHM of
<60 eV.

Proton Energy (keV)	Reaction	Gamma-Ray Energy (MeV)	Cross Section (mb)	Width (keV)	References (author and year)
473	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$				Br 56a
484	$\text{F}^{19}(\text{p},\alpha\gamma)\text{O}^{16}$	7.12, 6.92, 6.13	>32	0.9	Bo 58, Bu 56, Ch 50
496	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$	6.36, 4.24, 4.21 ?		5	Hu 55, Hu 54, Kl 54
500	$\text{Si}^{30}(\text{p},\gamma)\text{P}^{31}$	7.75, 6.48, 4.62			Br 58, Br 56a
504	$\text{Al}^{27}(\text{p},\gamma)\text{Si}^{28}$	12.07		<0.20	An 58
506	$\text{Al}^{27}(\text{p},\gamma)\text{Si}^{28}$	10.29		<0.17	An 58
511	$\text{Na}^{23}(\text{p},\gamma)\text{Mg}^{24}$	10.8, 8.0, 6.9		0.8	Ba 56, Gr 55, Ha 55
513	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$			3	Hu 55, Hu 54, Kl 54
530	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$			3	Hu 55, Hu 54, Kl 54
532	$\text{C}^{14}(\text{p},\gamma)\text{N}^{15}$	10.7, 5.3			He 58, Ba 55
540	$\text{P}^{31}(\text{p},\gamma)\text{S}^{32}$				Ke 56, Gr 51, Ta 46
550	$\text{C}^{13}(\text{p},\gamma)\text{N}^{14}$	8.06, 4.11	1.44	32.5	Br 57, Wo 53, Se 52
580	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$	6.85 ?, 6.43, 4.28			Kl 54, Ta 54
594	$\text{Na}^{23}(\text{p},\gamma)\text{Mg}^{24}$	10.9, 8.0, 7.0		2	Ba 56, Pr 56, Gr 55
594	$\text{S}^{32}(\text{p},\gamma)\text{Cl}^{33}$	2.86, 2.05, 0.806			Va 56a
597	$\text{F}^{19}(\text{p},\alpha\gamma)\text{O}^{16}$	7.12, 6.92, 6.13	7.1	30	Hu 55a, Ch 50, Bo 48
607	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$	6.88 ?, 6.46, 4.34			Kl 54, Ta 54
612	$\text{Al}^{27}(\text{p},\gamma)\text{Si}^{28}$			<1	An 58, Br 47, Ta 46
625	$\text{Si}^{30}(\text{p},\gamma)\text{P}^{31}$	7.87			Br 58, Br 56a, Ts 56
630	$\text{O}^{18}(\text{p},\gamma)\text{F}^{19}$	8.5		2.6	Bu 55
632	$\text{Al}^{27}(\text{p},\gamma)\text{Si}^{28}$	10.41, 7.59, 1.77		<0.06	An 58, Ru 54, Br 47
636	$\text{Ne}^{22}(\text{p},\gamma)\text{Na}^{23}$	9.40			Th 58, Br 47a
640	$\text{C}^{14}(\text{p},\gamma)\text{N}^{15}$	10.8, 5.3			He 58, Ba 55
648	$\text{P}^{31}(\text{p},\gamma)\text{S}^{32}$			17	Ke 56, Fr 51, Gr 51
650	$\text{Ca}^{40}(\text{p},\gamma)\text{Sc}^{41}$				Bu 58
654	$\text{Al}^{27}(\text{p},\gamma)\text{Si}^{28}$	10.43, 7.61		<0.06	An 58, Br 47, Ta 46
660 ?	$\text{Ne}^{22}(\text{p},\gamma)\text{Na}^{23}$				Th 58, Br 47a
661	$\text{Mg}^{26}(\text{p},\gamma)\text{Al}^{27}$	7.88, 6.68, 5.9			Va 56b, Ru 54a
667	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$				Kl 54, Ta 54
672	$\text{F}^{19}(\text{p},\gamma)\text{Ne}^{20}$	11.88, 1.63	0.5	6.0	Fa 55, Hu 55, Si 54
672	$\text{F}^{19}(\text{p},\alpha\gamma)\text{O}^{16}$	7.12, 6.92, 6.13	57	6.0	Hu 55a, Ch 50, Bo 48
675	$\text{B}^{11}(\text{p},\gamma)\text{C}^{12}$	12.15, 4.43	0.050	322	Hu 53
675	$\text{Na}^{23}(\text{p},\gamma)\text{Mg}^{24}$	11.0, 8.1, 7.1		≤ 1	Ba 56, Pr 56, Fl 54
675	$\text{Mg}^{25}(\text{p},\gamma)\text{Al}^{26}$	6.55, 5.21, 3.30			Gr 56, Ka 55, Kl 54
675	$\text{Si}^{30}(\text{p},\gamma)\text{P}^{31}$	7.92, 6.65, 1.27			Br 58, Br 56a



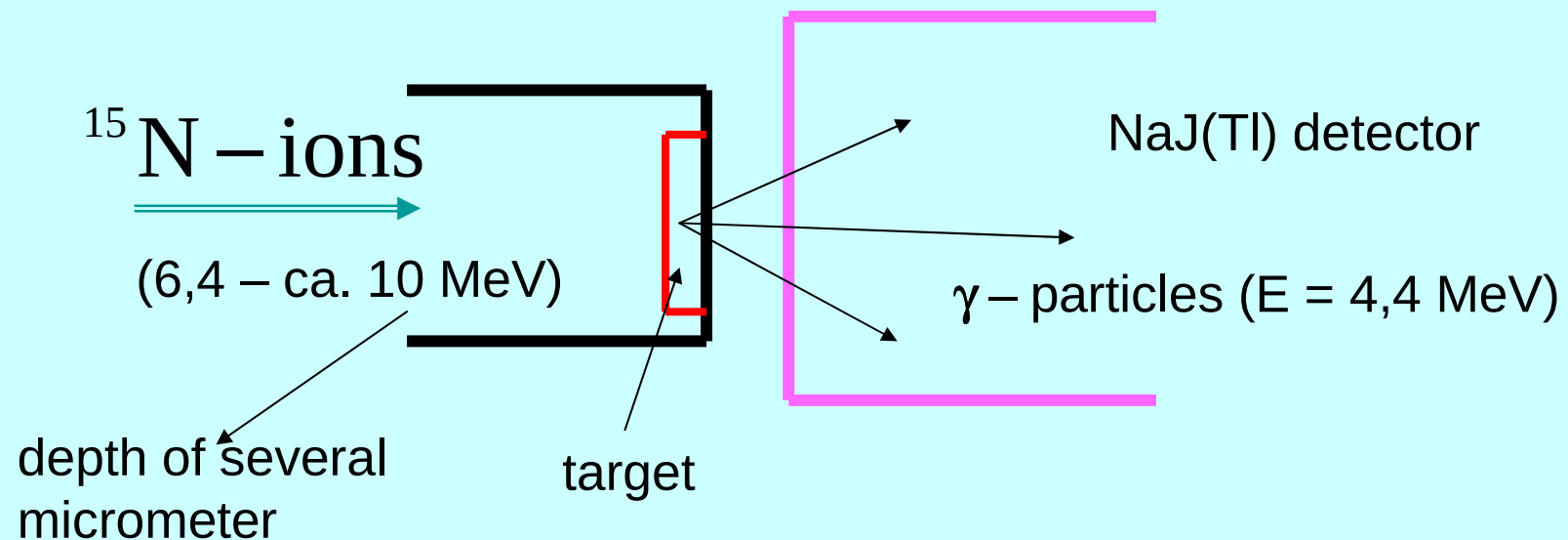


Resonance profiling of Al concentration in Si: (a) schematic diagram of the sample, (b) gamma-ray profiles as a function of proton energy

N-15 method

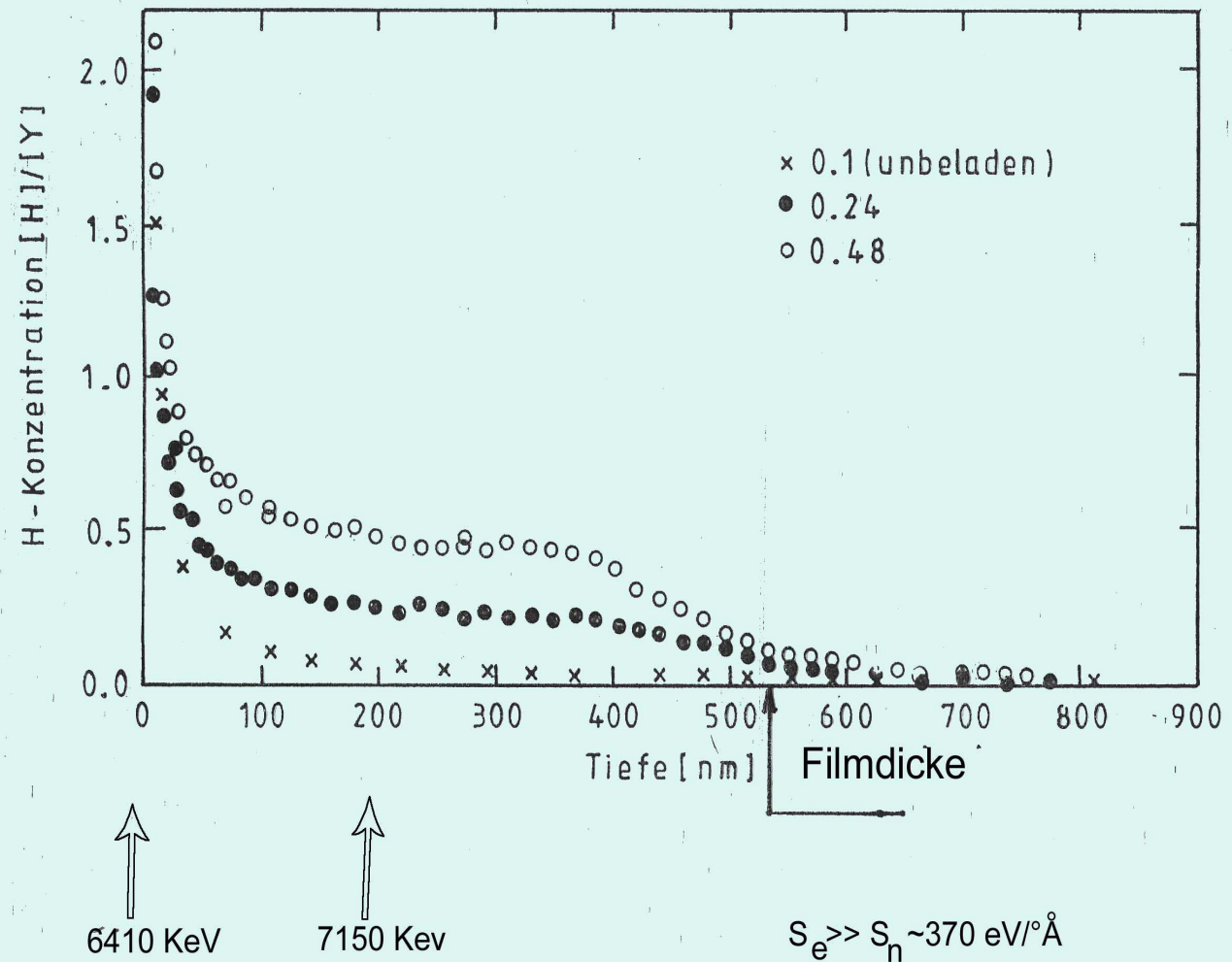
H-profiling using the ${}^1\text{H}({}^{15}\text{N}, \alpha\gamma){}^{12}\text{C}$ reaction

Determination of concentration and depth profile of H



sensitivity of
sintered Y-Ba-Cu-
O high- T_c
superconductors
for humidity and H
charging

H-Tiefenprofile zur Bestimmung der H-Konzentration (N-15 Methode)

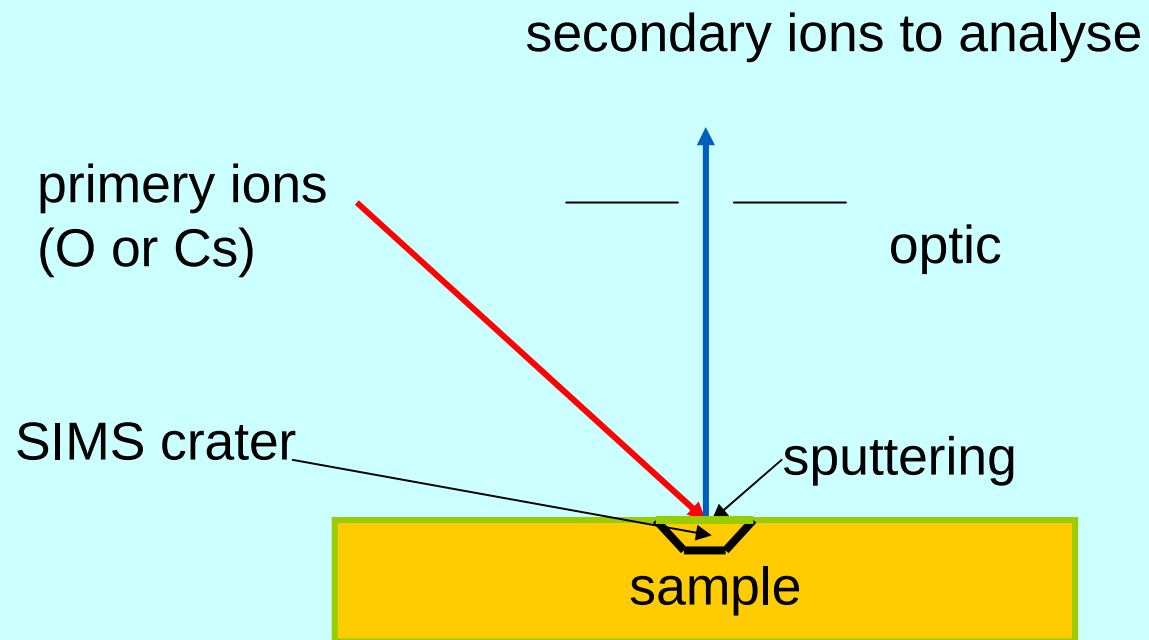




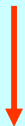
Secondary Ion Mass Spectrometry (SIMS)



The principle



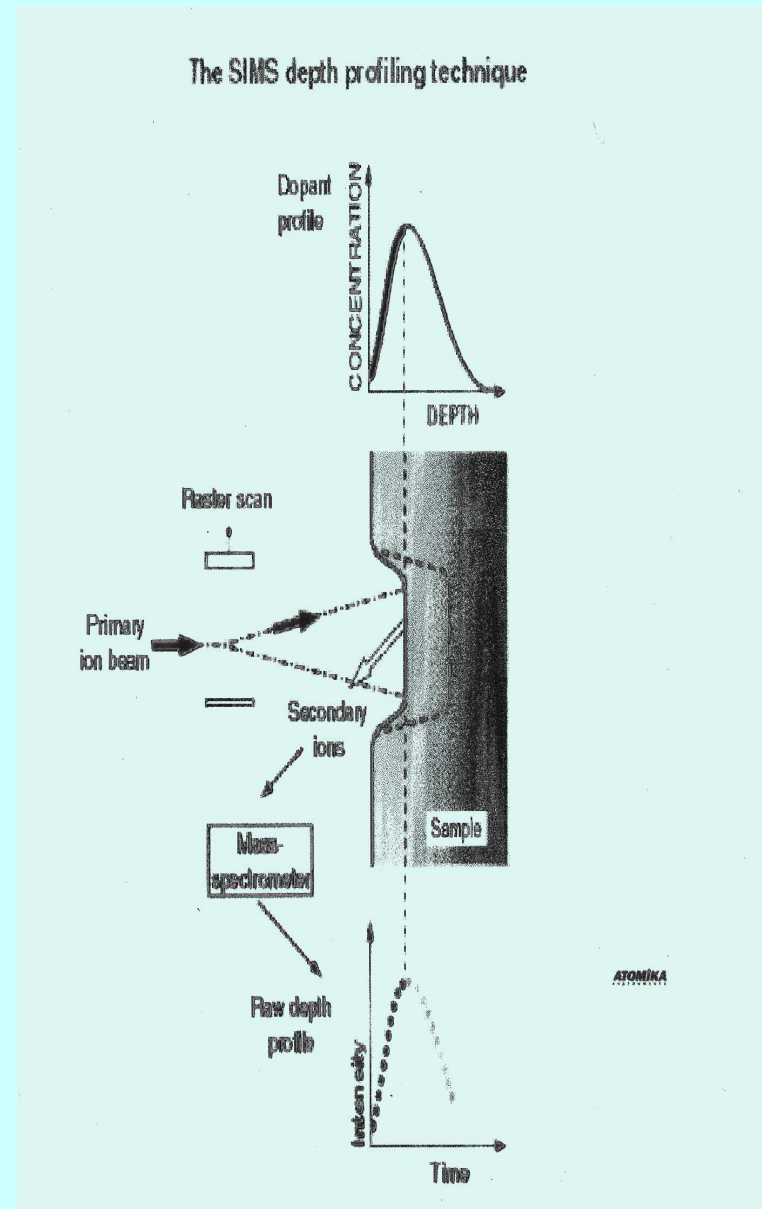
primary ions sputter the
surface



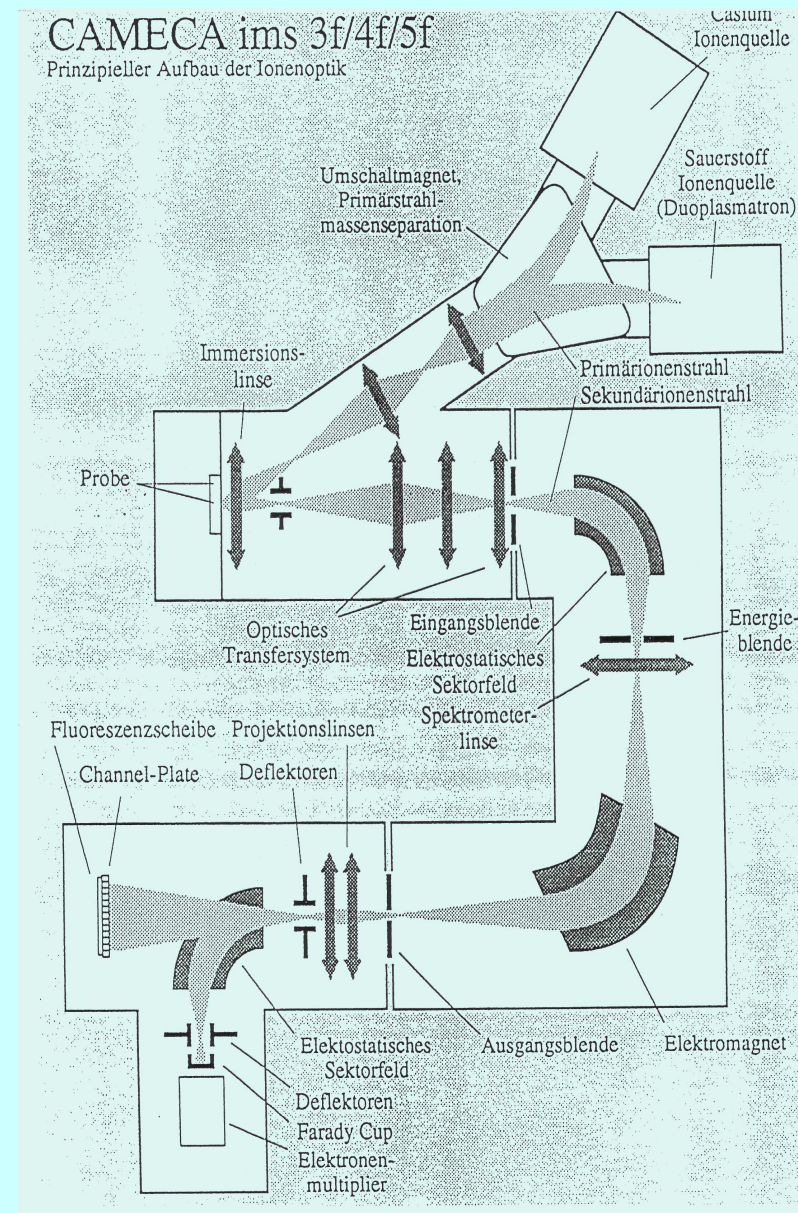
formation of SIMS crater
and depth profile



transformation of sputtering
time into depth (frequently
difficult)



schematic set-up of the
SIMS equipment at the
Institute of Materials Science
of the TUD



Different measurements modi

point analysis (micro analysis)
mass spectrum of microscopical spots

x-y

z

lateral element distribution
(imaging)

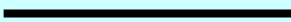
depth profile

3-D element distribution
(3D imaging)



different beam modi

Point measurement 

Line measurement 

Scanning modus 

Point resolution is determined by the diameter of the beam spot.
It figures out about 1-3 micrometer.

The scanned area is typically between 150 und 250 μm^2

Small beam spots result in decreased element sensitivity
because of the low ionic currents.

Limit of detection

is determined by the interaction between:

spot diameter }
layer thickness } volume
ionic current }

For example:

<u>limit</u>	<u>spot</u>	<u>depth</u>	<u>volume</u>
1 ppm	1 μm	1000 nm	0.785 μm^3
1000 ppm	1 μm	1 nm	0.000785 μm^3
1 ppm	10 μm	10 nm	0.785 μm^3



depth profile:

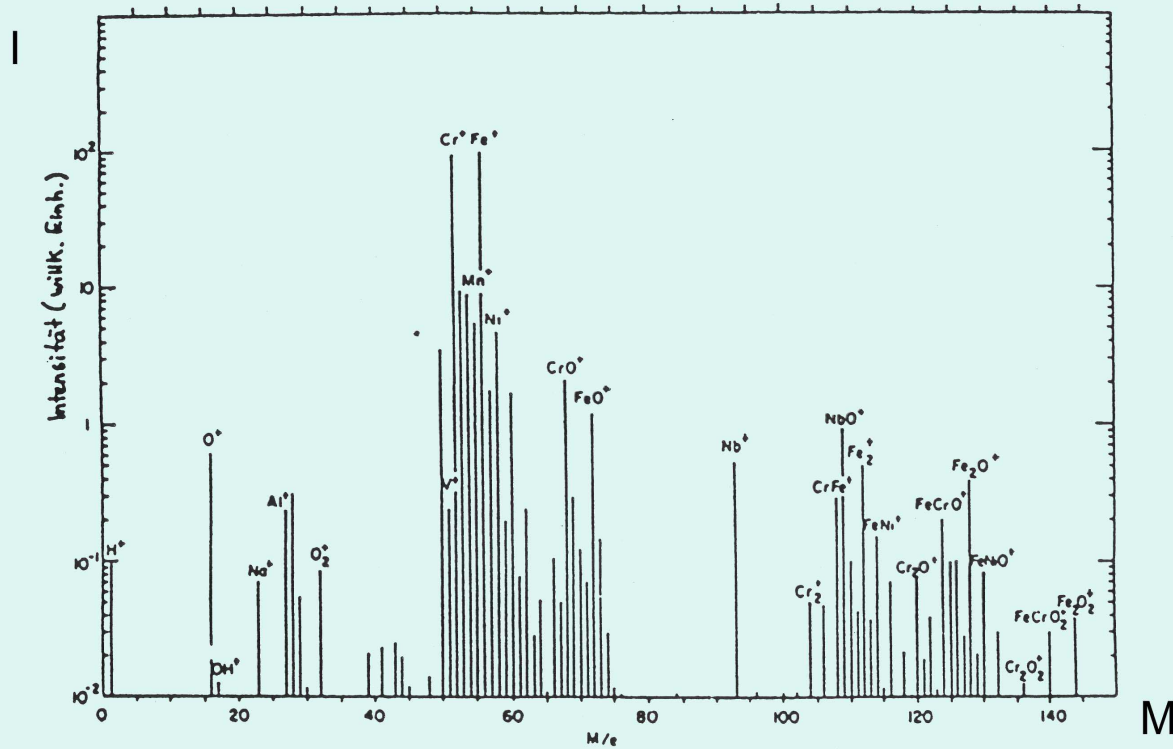
sputtering process	→	sputtering time
SIMS crater	→	depth

The time to depth conversion is difficult because of the preferential sputtering process (NRA is here in advantage).

depth resolution:

Theoretically just a couple of atomic rows, in practice 5-10 nm because of the roughness of the samples (comparable with RBS)

SIMS mass spectrum





Some applications

depth profile of H in Si

concentration of B in Si

Al depth profile in GaAs multilayer

comparison between SIMS und RBS measurements in Si/CoSi/Co₂Si/Co thin film sample

Ti-diffusion in Ni-Zr-Al sample

O-diffusion in PZT ferroelectrics

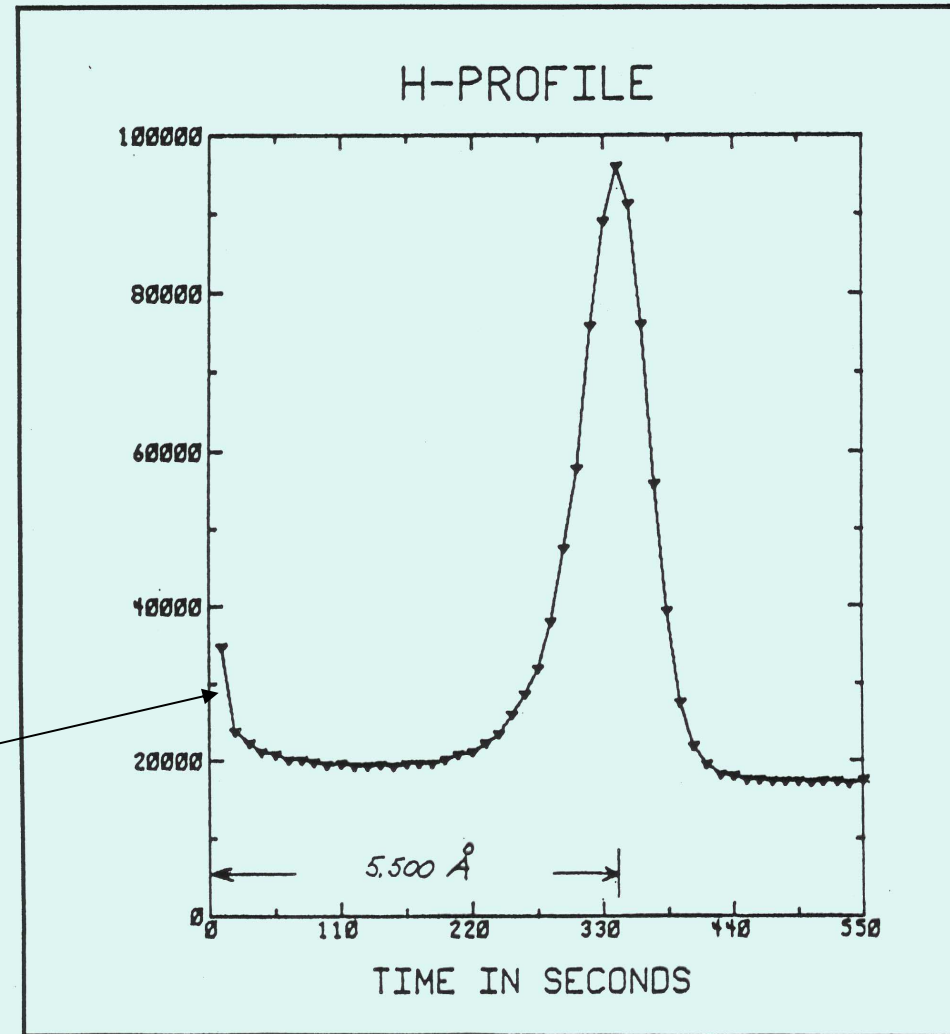


Depth profile of implanted
H in Si.

The maximum of the H
peak is in a depth of 550
nm.

surface peak

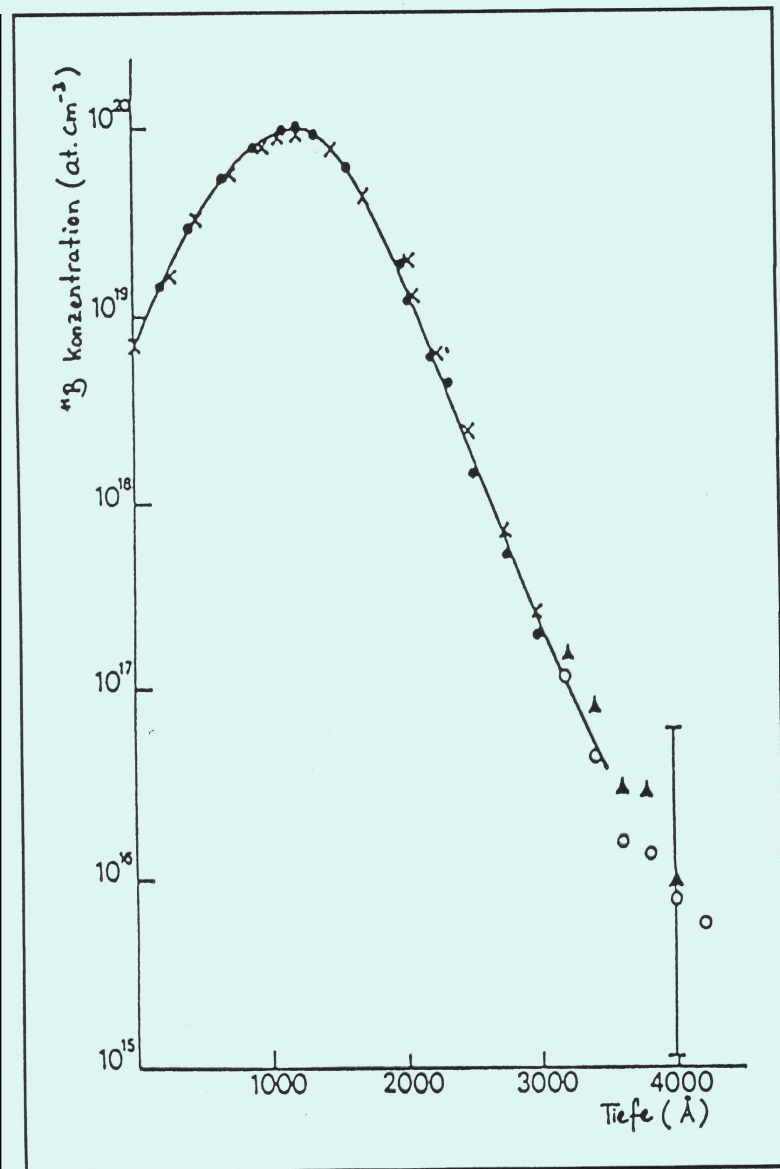
SIMS



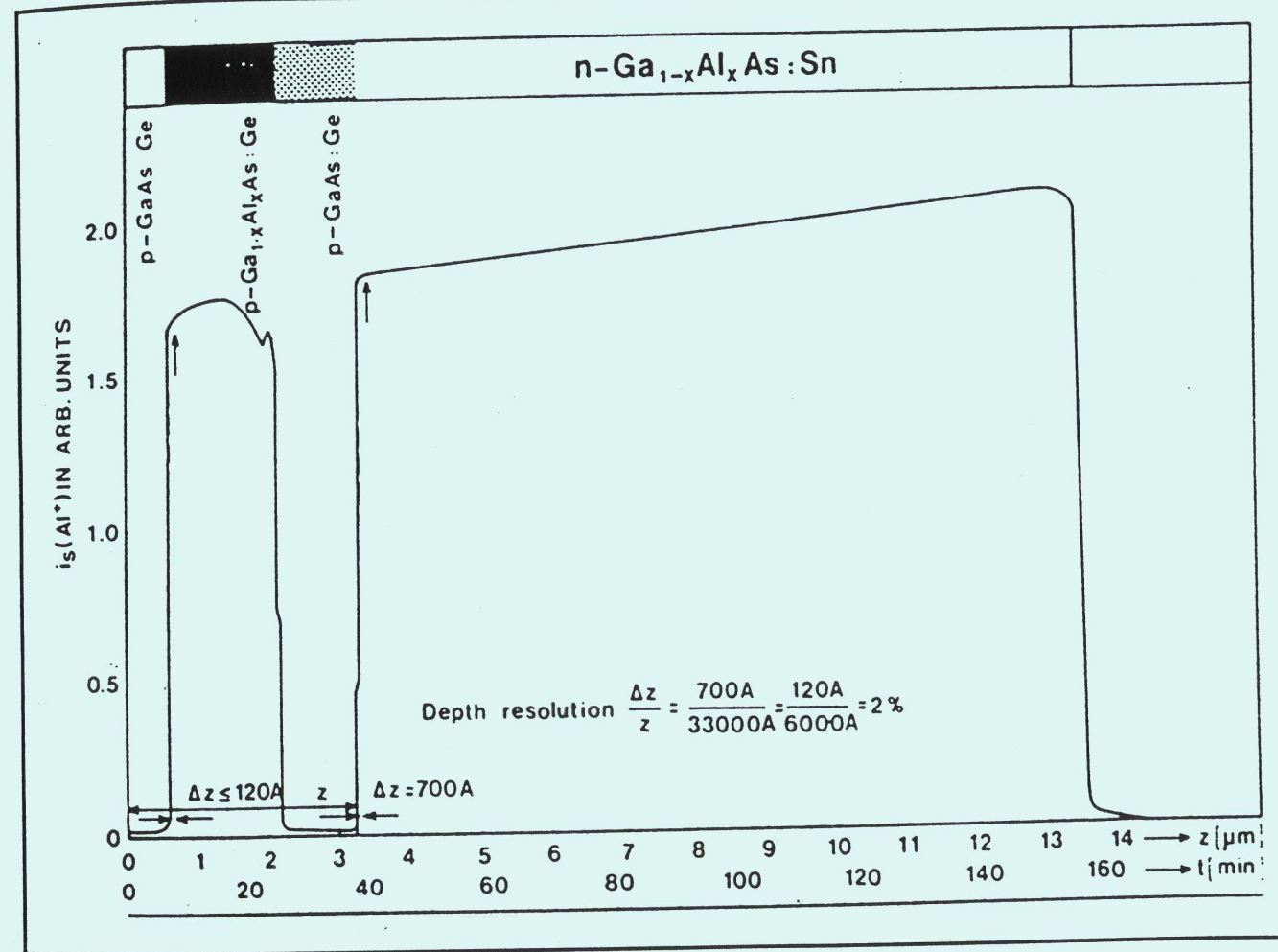
H-Tiefenprofile in Si

B in Si

The concentration profile of B was determined between 10^{16} and 10^{20} atom/cm³ over 4 order of magnitude



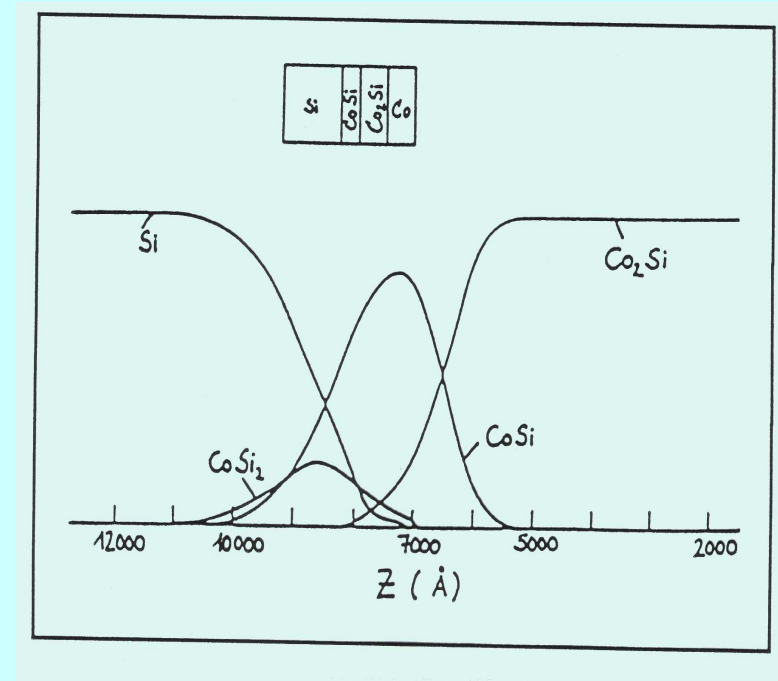
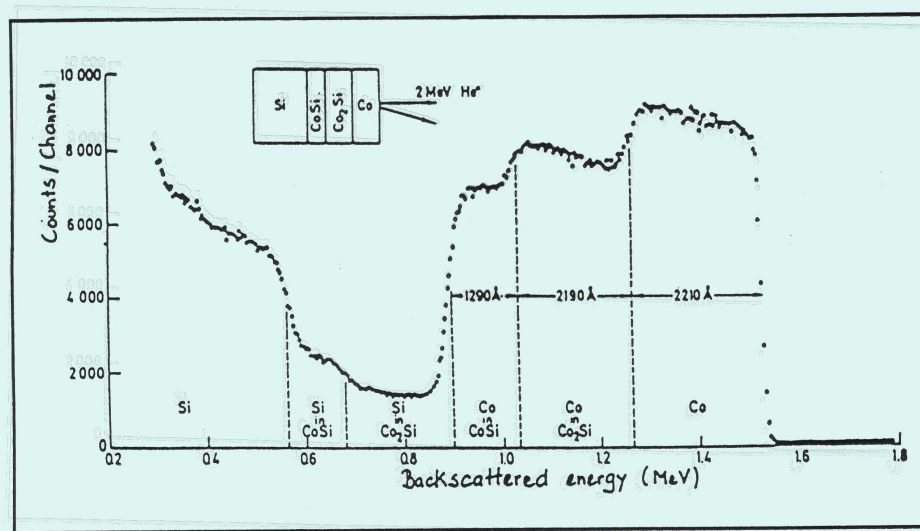
Monitoring of Al in a GaAs thin film system



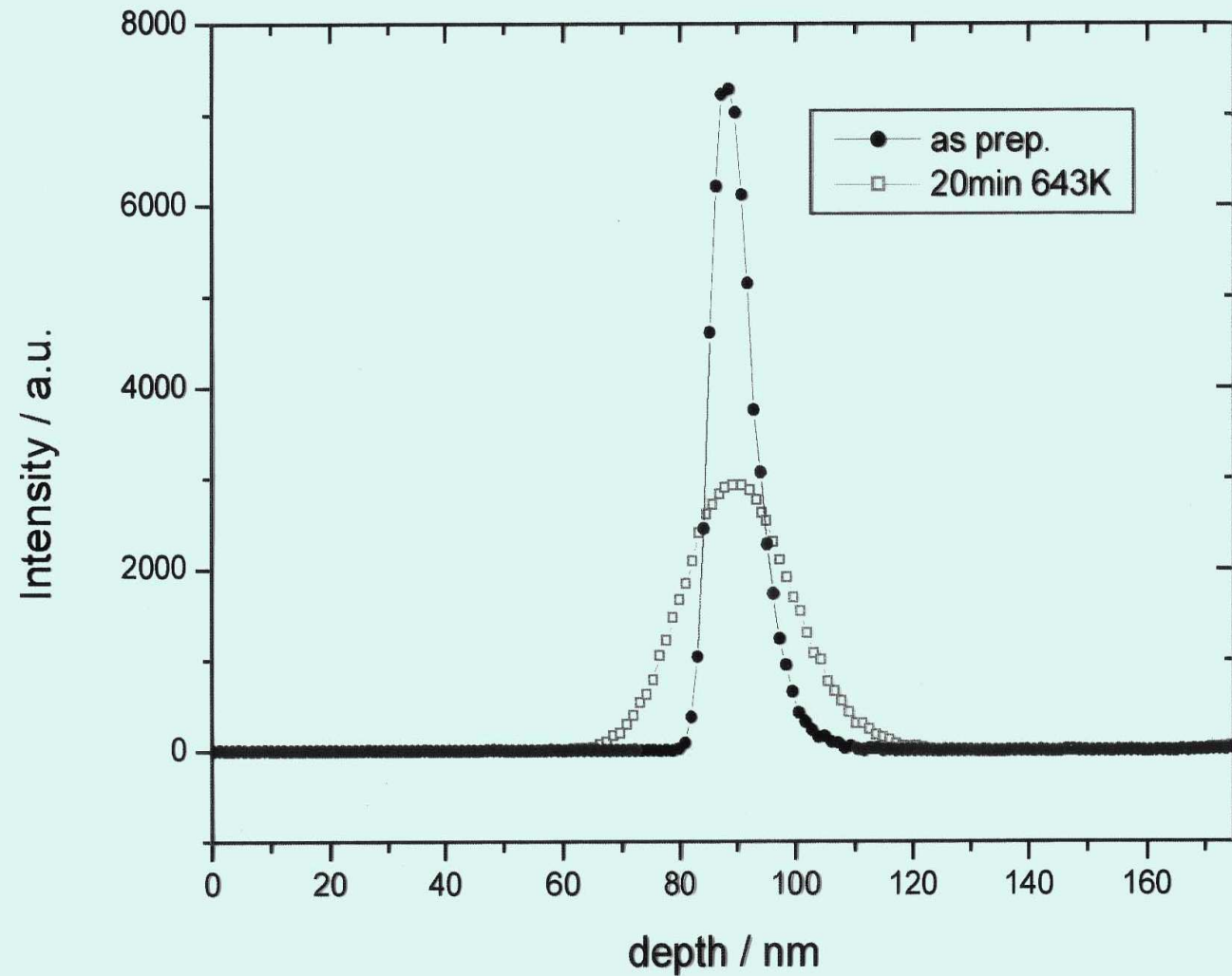
Comparison between RBS and SIMS spectra of a Co/Co₂Si/CoSi/Si thin film sample

RBS

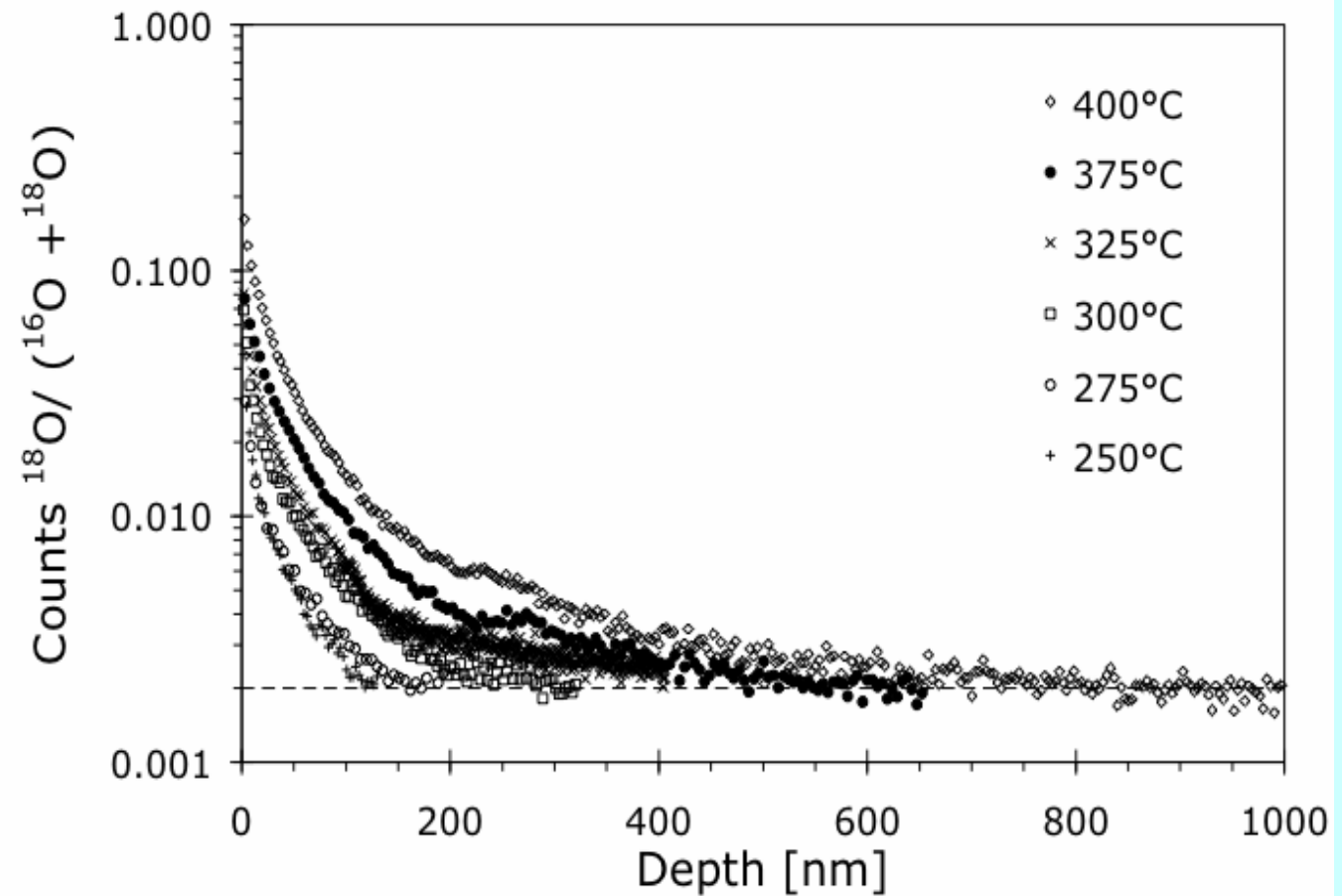
SIMS



Ti-diffusion in a $\text{Ni}_{23}\text{Zr}_{62}\text{Al}_{15}$ sample



^{18}O depth profile in
PZT (Pb-Zr-Ti-O)
ferroelectric
samples





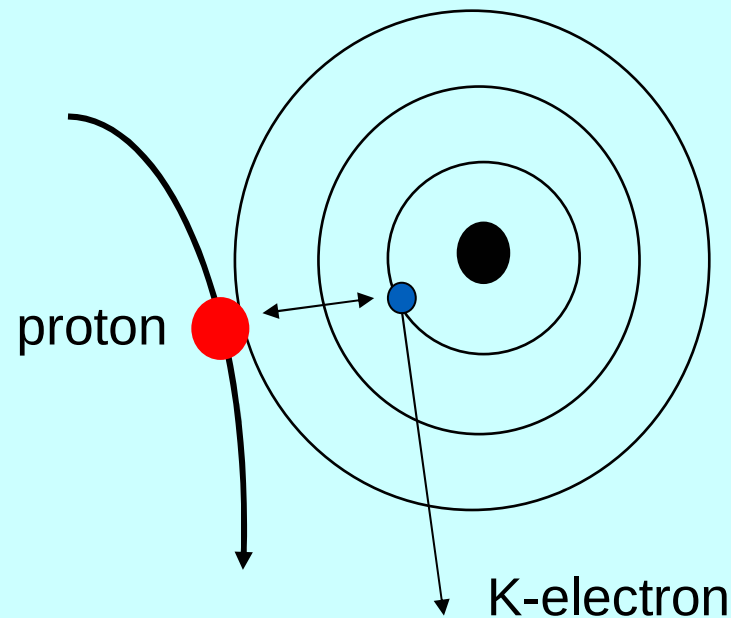
Particle Induced X-Ray Emmission/ Proton Induced X-ray Emission (PIXE)



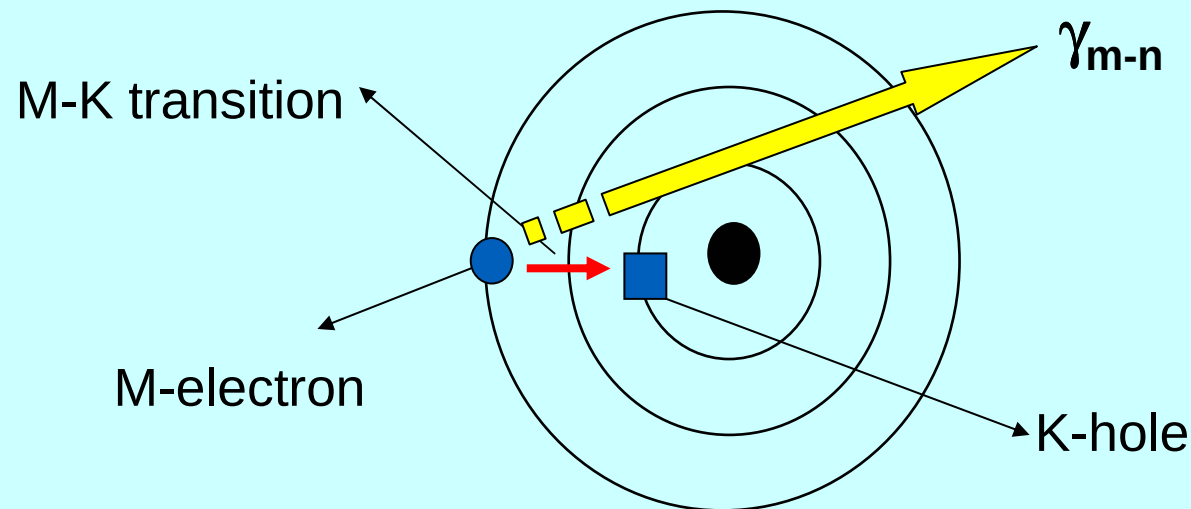
Principle of proton induced x-ray emission

First step:

electrons from the inner shells (frequently K-electrons) will be kicked out by primary protons with a typical energy of 1-2 MeV.



second step:
the electron hole will be filled up by electrons from higher shells.
Hereby **characteristic x-ray emission** with **element specific frequency** and **concentration dependent intensity** will be created.



$$E = h\nu \Rightarrow \nu_{m-n} = \frac{E_m - E_n}{h} = \frac{2\pi^2 m_e^2 e^4}{h} \left(\frac{1}{m^2} - \frac{1}{n^2} \right)$$

important features:

excellent sensitivity (about one order of magnitude better as of the electron micro probe)

poor depth resolution, because x-ray emission has to be detected

good lateral mapping of trace elements if combined with a proton micro beam

non-destructive

Why is the sensitivity so excellent?

The reason is the strong reduction in the background, which is caused by the bremsstrahlung. Bremsstrahlung has a continuous energy distribution and will be produced always if electrons will be slowed down by a solid.

$$I(\text{Bremsstrahlung}) \approx \frac{1}{M(\text{projectile})} \Rightarrow I_{\text{protons}}^{\text{BS}} \ll I_{\text{electrons}}^{\text{BS}}$$

As a consequence, the sensitivity of PIXE is much more better than of EMPA



some applications

biology

trace element analysis

enviromental research

air pollution

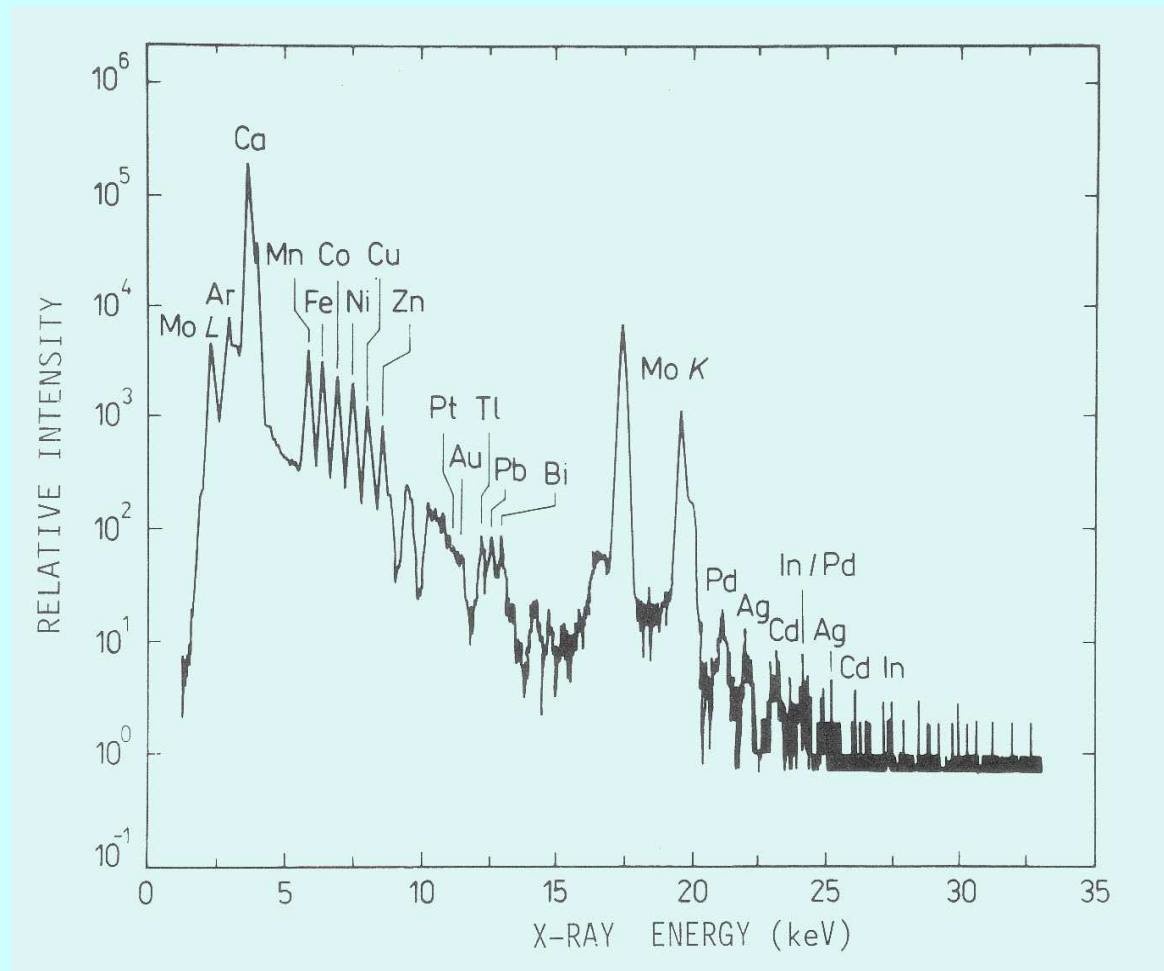
archeology

analysis of ancient paintings and
coins

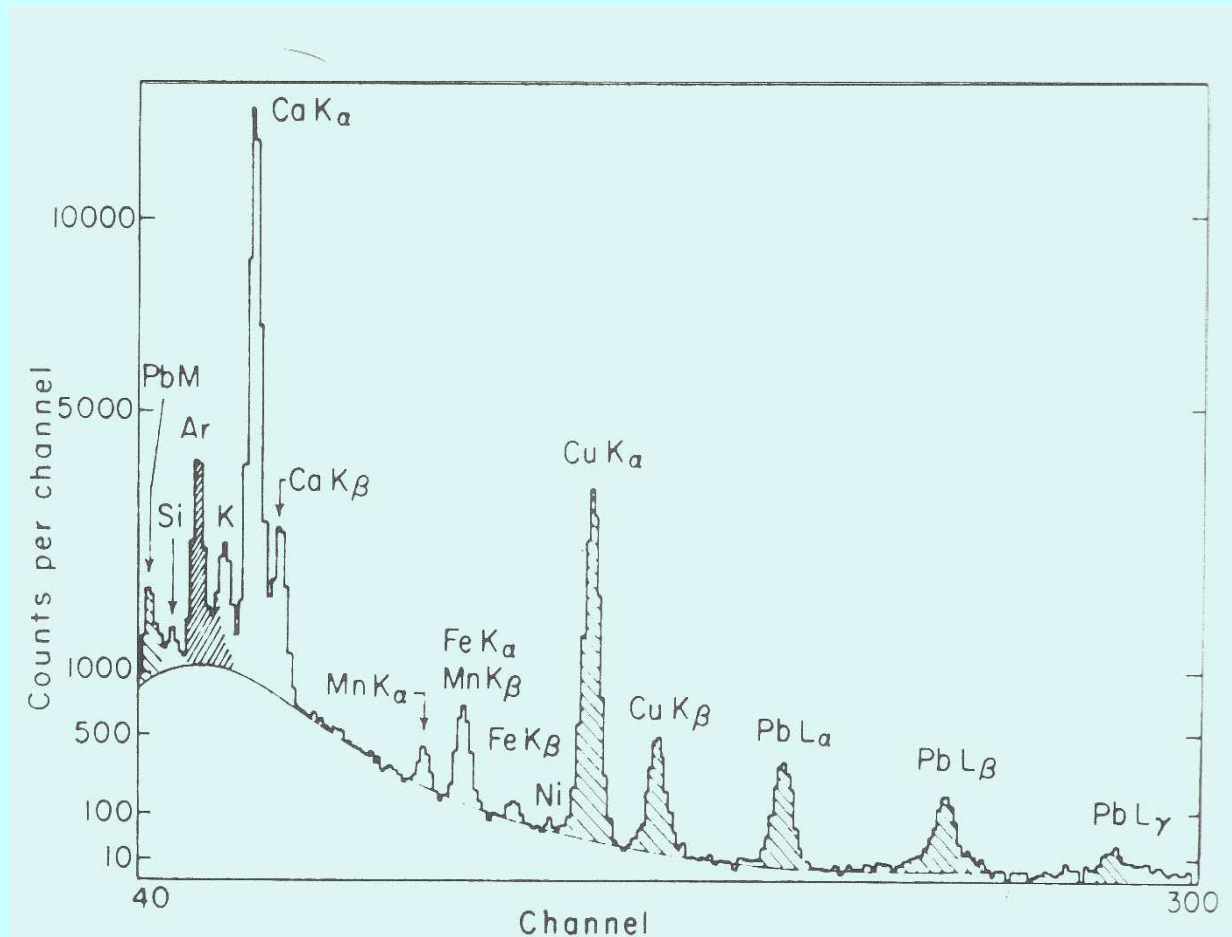
ion microscope

combined with strongly focused
ion beam, laterale mapping of
trace elements and multi element
analysis





PIXE spectrum of an aqueous sample containing only 10 μ g of each of the investigated elements



X-ray spectrum of ink on paper from the Gutenberg Bible

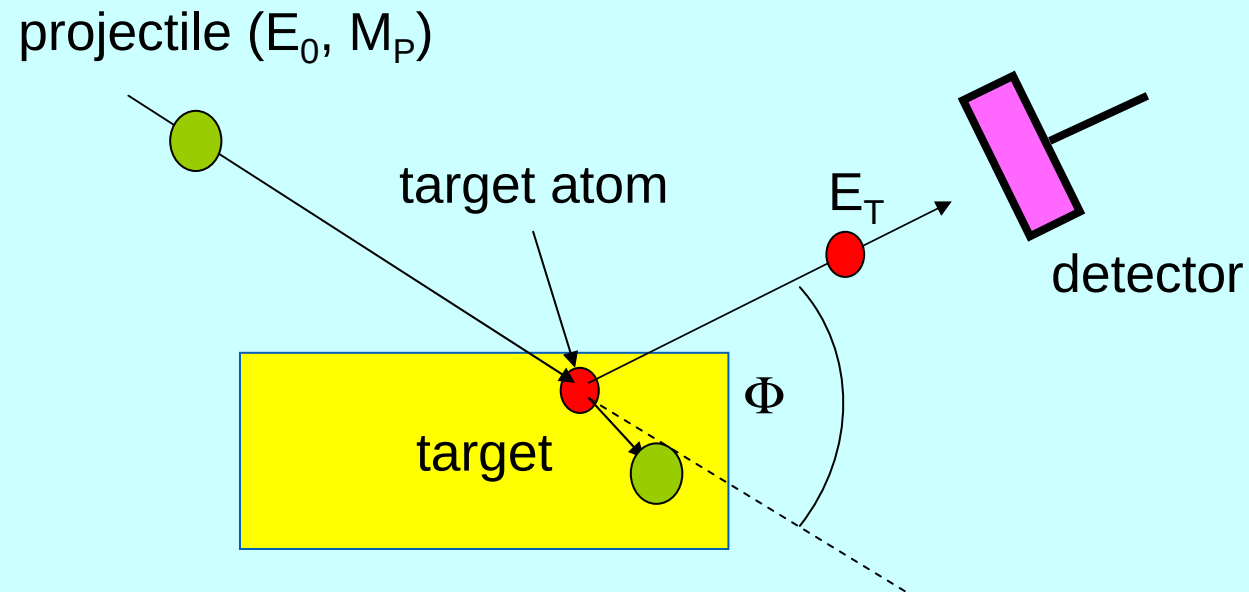


Elastic Recoil Detection Analysis

ERDA



principle of the method



$$K_{\text{ERDA}} = \frac{E_T}{E_0} = \frac{4 \left(\frac{M_P}{M_T} \right)}{\left[1 + \left(\frac{M_P}{M_T} \right) \right]^2} \cos^2 \Phi$$

The method is similar to an RBS measurement, however, instead of the backscattered primary ions the kicked out target atoms will be detected. This results in the **direct detection of the target atoms** and herewith the **determination of the composition of the target**. Also the energy of the detected target atoms will be measured, therefore, similarly to RBS, **depth profiles** can be defined.

The transferred energy has to be high in order to make it possible that a target atom will be kicked out from the sample. Therefore, heavy projectile are necessary, that will be scattered on the lighter target atoms $M_P > M_T$.

For ERDA measurements generally an energy of about 1 MeV/amu is necessary. In order to detect lighter target atoms like H, He, Li, N, C, O ($Z < 9$), one has to use heavier projectiles like Si, Cl or Ar correspond to an energy of 30-40 MeV. Furthermore it is possible to measure also H isotopes using a He beam.





benefits of the method:

- simple measuring technique
- direct detection of target atoms
- qualitative and quantitative analysis

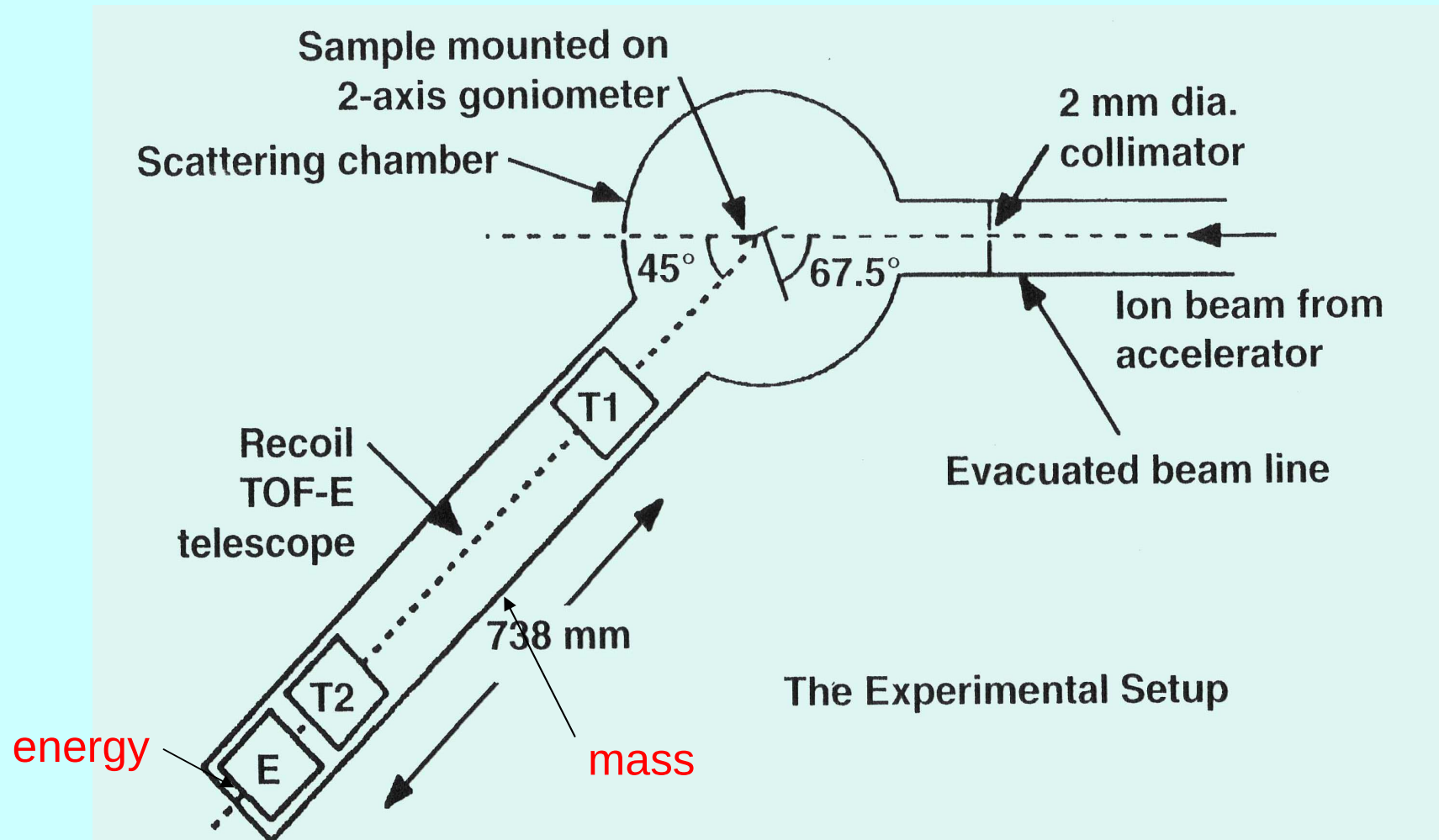
disadvantages:

- dept resolutuion is poorer
- sensitivity is poorer

Development of the method: time of flight (TOF) ERDA:
measurement of velocity (time) and energy of atoms

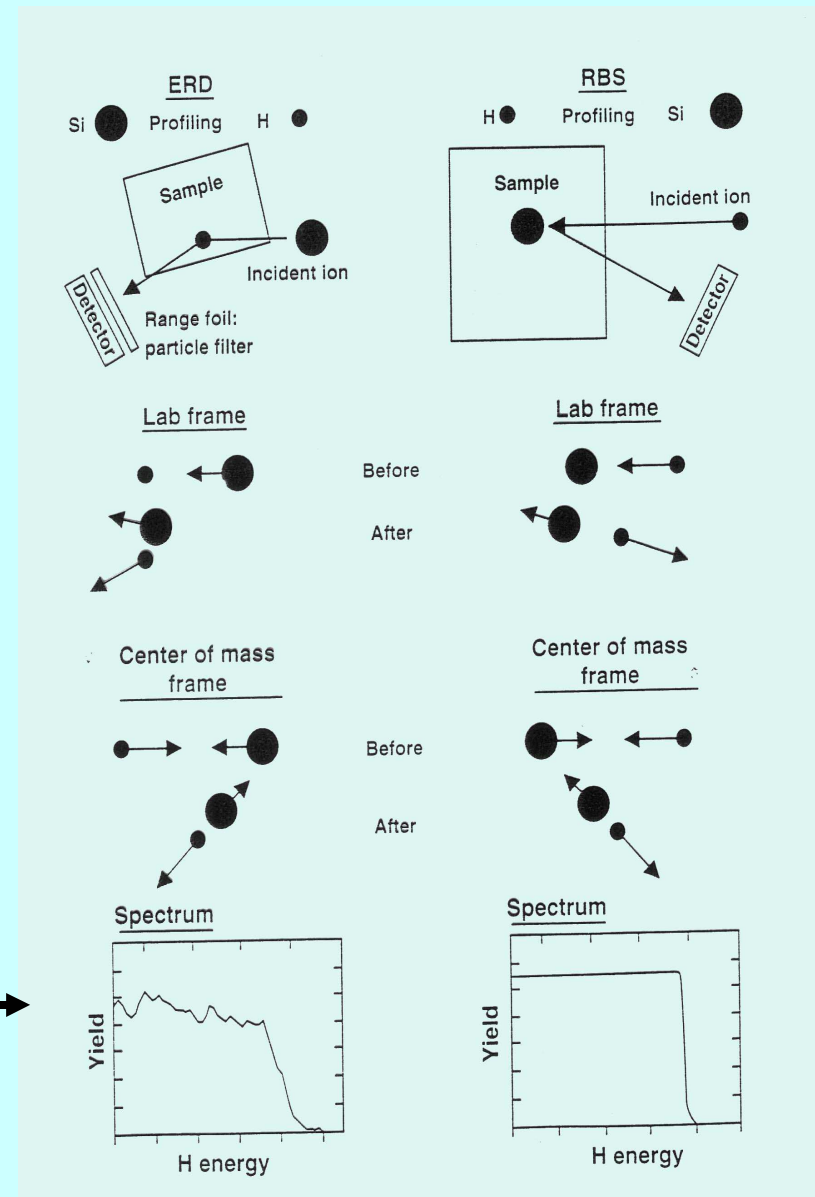


TOF ERDA set-up

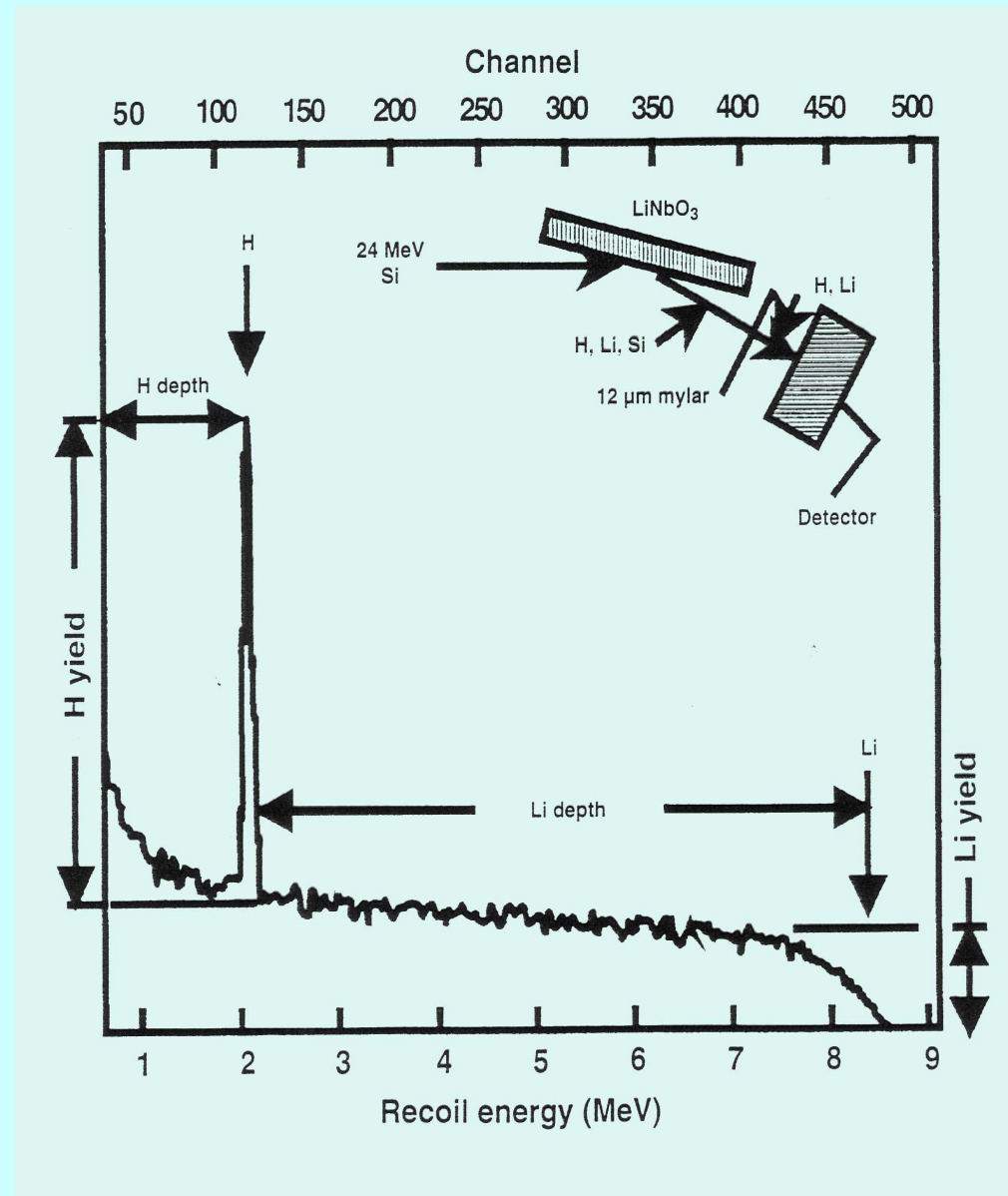


Comparison of ERDA and RBS geometry

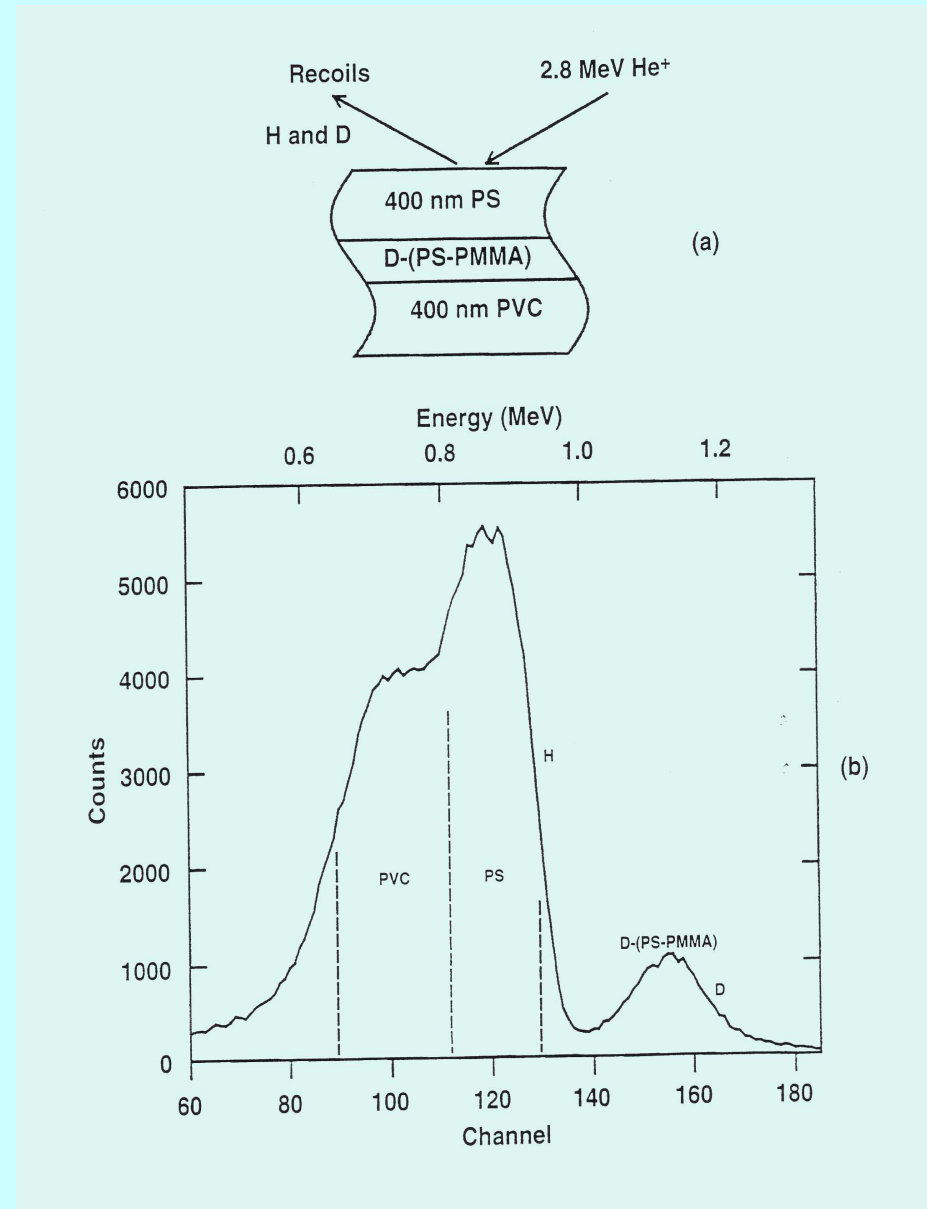
Straggling $\sim Z_1^2$



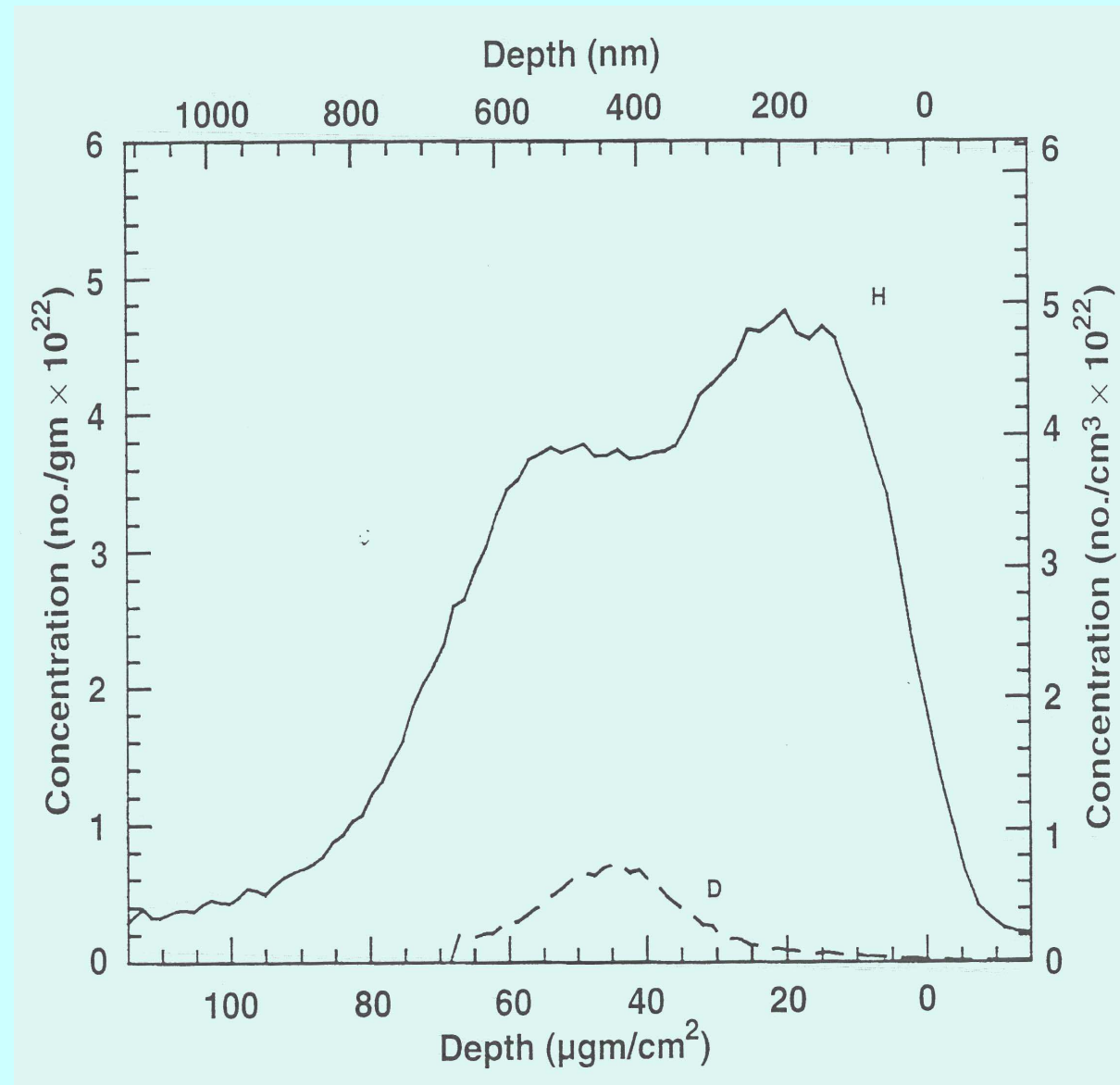
detection of H and Li in a
 LiNbO_3 sample using Si
projectiles



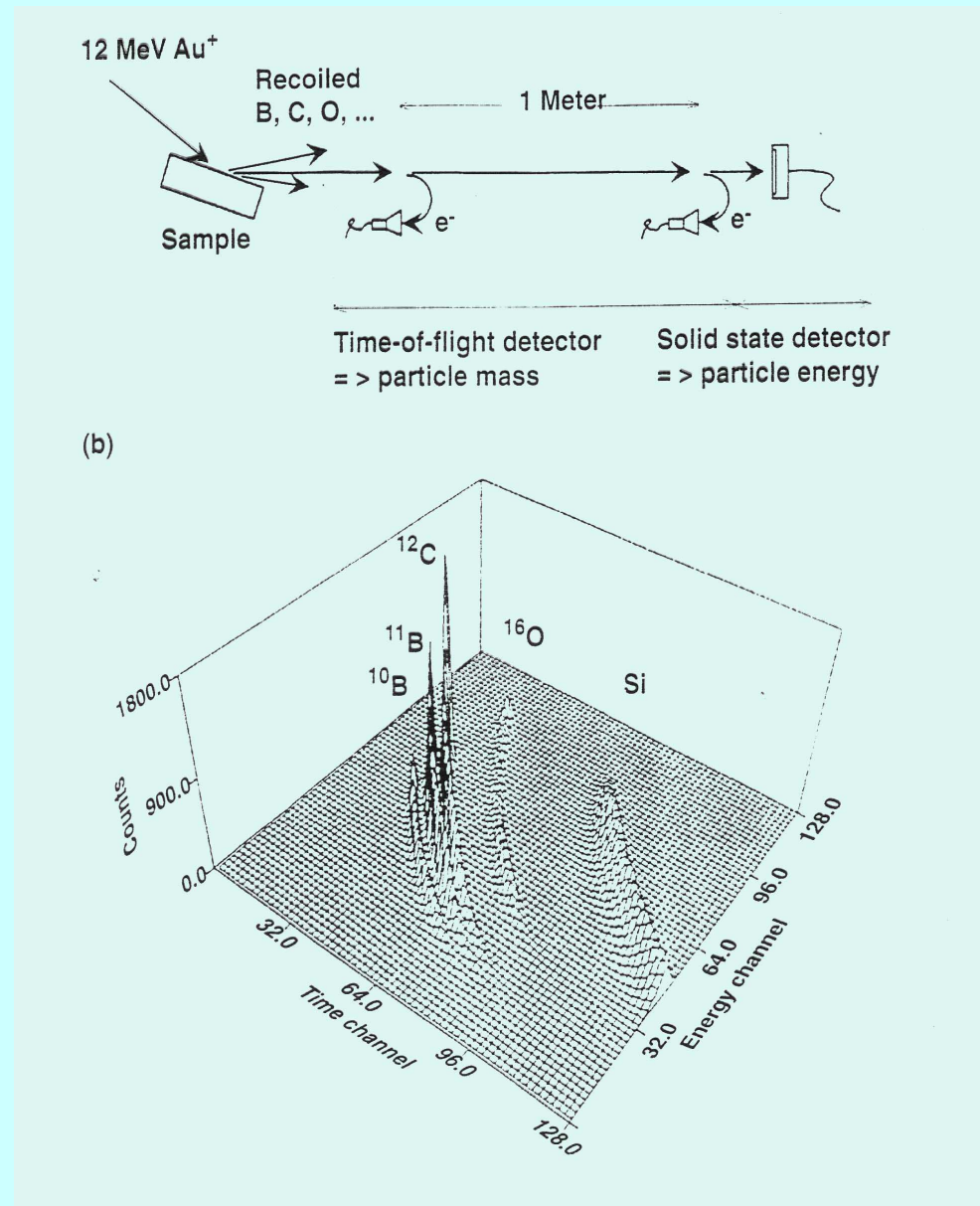
Detection of H and D in a thin polymer film using He projectiles



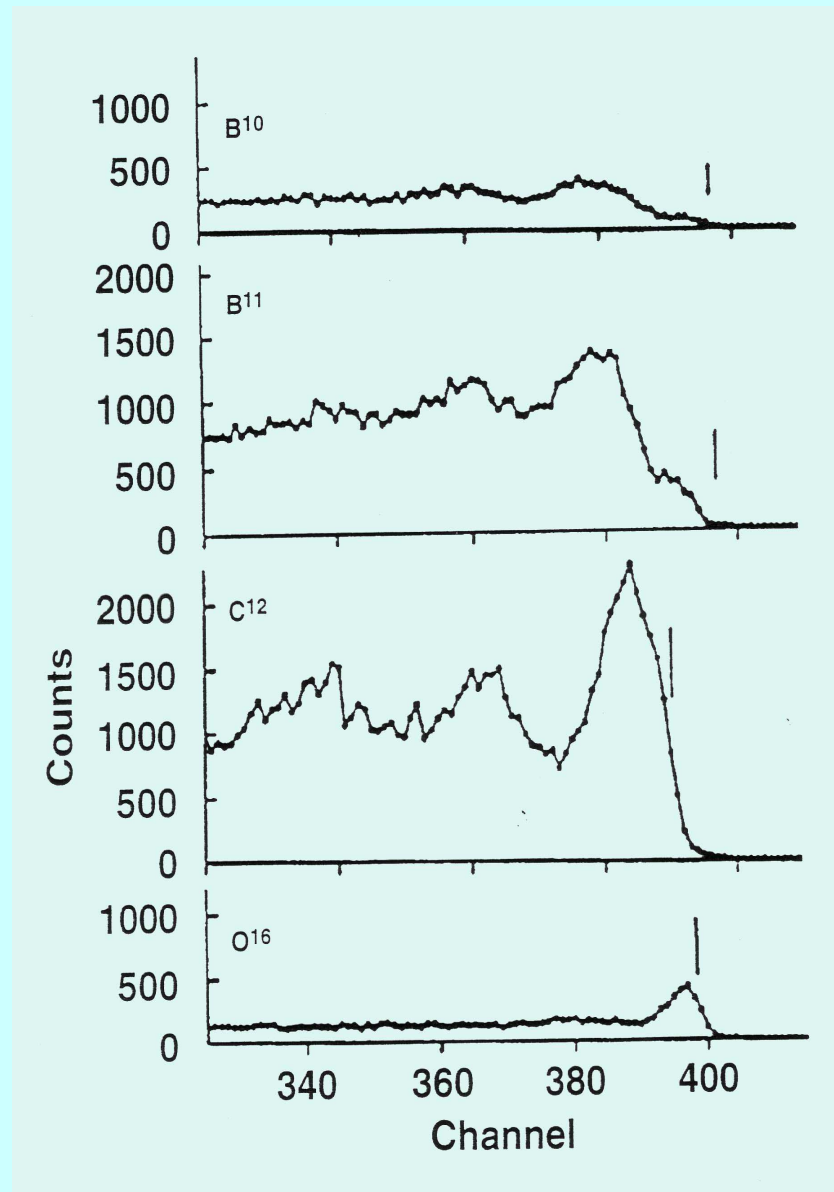
Concentration depth profiles of H and D



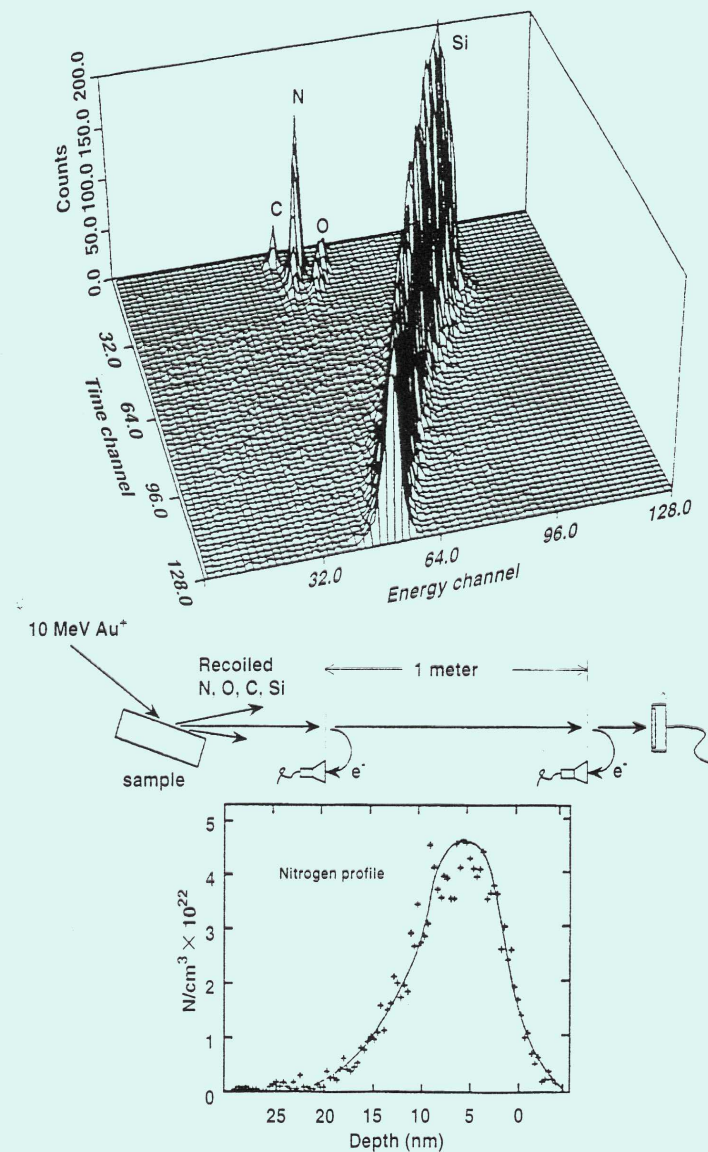
3D view of light elements measured using Au projectiles in a TOF ERDA set-up



Concentration depth profiles of B, C and O



N profiling in a SiN sample



Sensitivity of different analytical methods for surface analysis as a function of atomic number in an interference free situation

ESCA: electron spectroscopy for chemical analysis

LIMS: laser ionization mass spectroscopy

SIMS: secondary ion mass spectroscopy

RBS: Rutherford backscattering spectrometry

